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THERMAL CONTROL OF AN ELECTRONIC ENCLOSURE
UTILIZING A VAPOR CHAMBER

By

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B.S.M.E. University of Iowa, 1968

THESIS

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ABSTRACT

This thesis addresses the problem of extracting heat from sealed electronic enclosures. Typical industry practice is to use various air-to-air and air-to-liquid heat exchangers. These techniques are known to require costly custom designs.

This thesis points out how one can apply heat pipe technology in the form of a vapor chamber to solve this type of problem. The details on the design and testing of two prototype vapor chambers are cited.

Included in the text are typical industrial applications that require sealed enclosures to protect their associated electronic control hardware. Also mentioned is some historical background on heat pipes.

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LIST OF SYMBOLS

- A = Area (ft^2).
- a = Accomodation Or Sticking Coefficient, Dimensionless.
- b = Geometrical Form Factor, Dimensionless.
- b = Grid Spacing (inch).
- CFM = Air Flow (ft^3/min).
- C_r = Capillary Conductance. ($\text{ }/b$), Dimensionless.
- E_{tot} = Total System Energy (btu/hr).
- E = Modulus Of Elasticity (lb/in^2).
- h = U-Tube Manometer Height Differential (mm,inch).
- h_i = Internal Film Coefficient ($\text{btu}/\text{hr}\text{-ft}^2 \text{ }^\circ\text{F}$).
- h_o = External Film Coefficient ($\text{btu}/\text{hr}\text{-ft}^2 \text{ }^\circ\text{F}$).
- L = Latent Heat Of Vaporization (btu/lb).
- l_d = Distance Between Hot Spots (inch).
- l_w = Width Of Hot Spots (inch).
- p = Vapor Pressure (psia).
- P = Unknown Pressure (psia).
- P_a = Atmospheric Pressure (psia).
- Q = Energy In The Form Of Heat (btu/hr).
- Q_i = Input Energy (btu/hr).
- R = Universal Gas Constant ($\text{ft}\text{-lbf}/\text{lb}\text{-mole }^\circ\text{R}$).
- r_c = Condensation Rate Per Unit Area ($\text{lbm}/\text{hr}\text{-ft}^2$).
- r_c = Pore Size (inch).

- r_e = Evaporation Rate Per Unit Area (lbm/hr-ft^2).
 S.P = Standard Pressure (1 atm, psia).
 T = Absolute Temperature ($^{\circ}\text{R}$).
 T_i = Inside Enclosure Temperature ($^{\circ}\text{F}$).
 T_a = Room Ambient Temperature ($^{\circ}\text{F}$).
 T_o = Room Ambient Temperature ($^{\circ}\text{F}$).
 t = Plate Thickness (inch).
 t = Time In Minutes.
 t_w = Screen Thickness (inch).
 U = Internal Energy (btu/hr).
 U = Overall Heat Transfer Coefficient ($\text{btu/hr-ft}^2\text{ }^{\circ}\text{F}$).
 w = Load (lb/in^2).
 W = Energy In The Form Of Work (btu/hr).
 y = Maximum Deflection (inch).
 α = Shape Factor, Dimensionless.
 γ = Surface Tension (dynes/cm, lbs/hr^2).
 ϵ = Wick Porosity, Dimensionless.
 ν = Kinematic Viscosity (ft^2/hr).
 ρ_a = Density Of Air (lb/ft^3).
 ρ_{hg} = Density Of Mercury (lb/ft^3).

CHAPTER I

INTRODUCTION

TODAY'S INDUSTRIAL MARKET

In today's industrial market place there is a continual demand to produce cost effective products. One way in which the electronics producers have endeavored to satisfy this need is by more sophisticated control packages at competitive prices. Competition has forced the electronics manufacturer to invest high sums of money in research and development to provide more and more capability at lower prices. This increased capability at lower prices has manifested itself in shrinking package sizes as is witness the hand held calculator and larger digital and analog computer systems.

TECHNOLOGICAL RESULTS

Although technology has resulted in super sophisticated computer systems to be contained in high density packages, it has also resulted in creating very sensitive products. For example, many integrated circuits begin failing exponentially above 70°C (158°F). Although at first glance this seems like a relatively high temperature compared to ambient room temperature, one must not lose sight of the fact that these integrated circuits are

buried inside a high density electronic package. These high density packages are often accompanied by other similar packages in a system and these systems in today's applications are being subjected to more and more hostile environments. The reason for this subjection can best be understood by the following example.

ENVIRONMENTAL APPLICATIONS

A typical computer system to control a hot ingot rolling mill in a steel mill cost approximately \$150,000. This control system because of its heat sensitivity is installed in a specially designed environmental control room. It will cost upwards of \$1,000,000 to wire up the rolling mill to the computer control. The major reason for the high installation costs are due to extremely long signal wire runs and the special room to house the system control. The room, of course, insures proper temperature controls but, it also protects the various electronic circuits from conductive dirt that will cause failure. Similar examples can be cited for the control systems required in the petro-chemical industry where corrosive vapors and potential explosions result in high installation costs. Some process control manufacturers have attempted to solve the high installation costs in hostile environments by placing their electronic controls in various MEMA-rated sealed enclosure¹. These sealed enclosures are then placed closer to the actual process they are controlling.

TYPICAL HEAT TRANSFER TECHNIQUES

Some of the ways that process control manufacturers have attempted to maintain safe operating temperatures for their electronic packages in sealed enclosures are by installing various air-to-air and air-to-liquid heat exchangers. These heat exchanging techniques often require custom designs for each enclosure. These devices often require as much as 30% of the available enclosure space. The prime movers required to move the various working fluids often add to the heat load that they were intended to remove. The heat exchangers employing a liquid working fluid require the end user of the system to install costly remote supply lines or if the system is closed a more costly self-contained circulating system results. The various mechanical elements in these heat exchangers are subject to wear and must have continual maintenance to insure they do not cause a catastrophic failure in the system under control.

PROPOSED HEAT EXCHANGER CRITERIA

There is a definite need for a heat exchanging device that will effectively insure safe operating temperatures for high density computer control systems. Further, in order to be a cost effective control system in today's market it must be able to operate in extremely hostile environments.

A heat exchanging device capable of operating effectively

under the aforementioned conditions should have the following design characteristics:

1. The device should be able to work in conjunction with a sealed enclosure such as NEMA-12.
2. If the device requires prime movers it would be desirable that they do not add to the heat load of the enclosure.
3. It would be highly desirable that the device require a minimum of enclosure volume.
4. The device should be applicable to a variety of enclosure designs without requiring major changes.
5. The device should operate under a closed system not requiring external system supply lines.
6. The device should be able to transfer high heat rates when small temperature differences exist between internal and ambient operating conditions.
7. The device should be able to be manufactured in a cost effective manner.

After extensive study and first hand experience in trying to effectively cool sophisticated computerized control systems the author feels that the only heat transfer device known today that would satisfy the above design criteria would be some form of the device commonly referred to as a "Heat Pipe."

BASIC HEAT PIPE OPERATION

A heat pipe within a given temperature range performs like a high conductance thermal conductor. This device has been referred to as; a thermal siphon, reflux condensor, thermal diode,

two phase heat exchanger, as well as, many others. A typical heat pipe is constructed as shown in figure 1². The high conductance properties of a heat pipe are directly attributed to the properties and the processes that the internal working fluid undergoes while operating. This device can have heat transfer rates several orders of magnitude greater than the best solid conductor of the same dimensions. This is a qualitative remark, however, since heat transfer is not by pure conduction. The basic heat pipe consists of a sealed tube made from materials that are structurally and thermally acceptable for the application along with a small amount of vaporizable fluid. The heat pipe utilizes a boiling-condensing cycle with capillary-aided condensate return to the evaporator as shown in figure 1. The boiling-condensing cycle is essentially isothermal due to the fact that there is very little pressure drop experienced between the evaporator and condensor.

HISTORICAL BACKGROUND OF HEAT PIPES

Historically, these devices were first described in a patent issued to R.S.Gaugler in 1944². This patent was assigned to General Motors Corporation. This concept lay dormant until 1962 when L. Trefethen of General Electric proposed its application in the space program². Shortly thereafter in 1963, T. Wyatt of John Hopkins proposed this concept for temperature stabilization of a satellite². The heat pipe technology best known today was in effect re-established in 1963 by George Grover and his associates

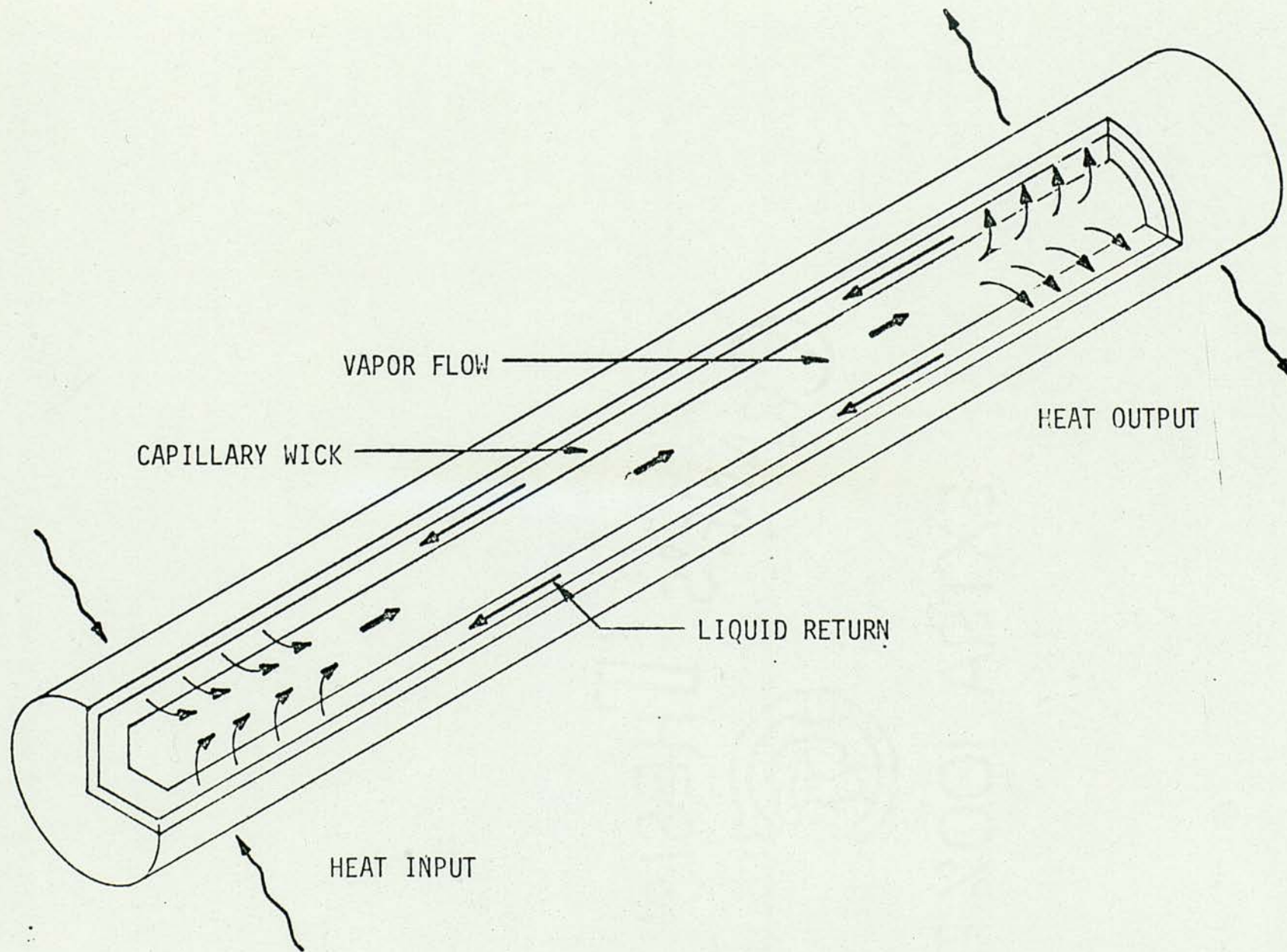


FIGURE 1. BASIC HEAT PIPE

of Los Alamos Scientific Laboratories². Since the re-establishment in 1963 many applications have surfaced. For example, RCA demonstrated a variable conductance device in 1964². The Air Force developed a cryogenic device in 1966³ and in 1967 the first heat pipe was flown under zero gravity conditions in space³.

VAPOR CHAMBER

After a literary survey, the author concluded that most applications of heat pipes have been on localized hot spot cooling. In order to satisfy sealed enclosure thermal control a more macro device is required. In fact, it turns out that a rectangular shaped chamber that can be mounted on top of a sealed enclosure best fits the geometry of the application rather than a cylindrical shape. Furthermore, since the enclosure will operate under gravity conditions a wick to pump condensate from the condensor to the evaporator via capillary action will probably not be required. Because of the discrete differences between the above described heat pipe, the author has elected to classify the device as a vapor chamber.

CHAPTER II

GOVERNING EQUATIONS, VAPOR CHAMBER ANALYSIS

INTRODUCTION

It is not the intent to this thesis to provide a detailed mathematical model of a vapor chamber but, to present a qualitative approach pointing out those parameters and considerations that should be included. Most of the specific details in this design application will be discussed in CHAPTER III.

CONSERVATION OF ENERGY

A convenient starting point in the analysis would be to apply the conservation of energy principles to the vapor chamber. From conservation of energy we know that the rate of creation of energy in a system must equal zero. That is:

$$\text{Energy Outflow} - \text{Energy Inflow} + \text{Energy Stored} = 0 \quad (1)$$

First, let's define the closed system as the vapor chamber as depicted in figure 2.

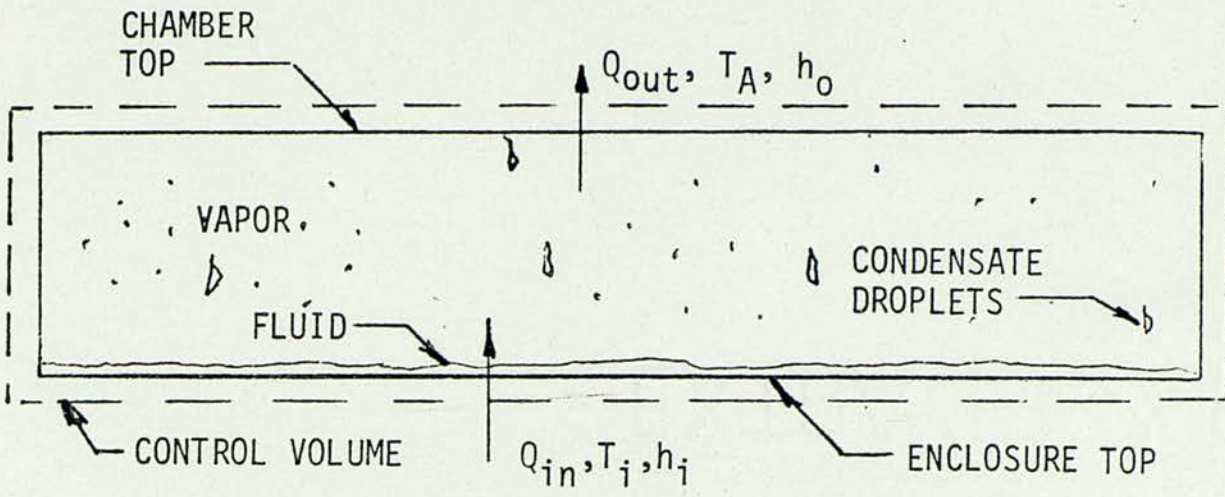


FIGURE 2. VAPOR CHAMBER CONTROL VOLUME

FIRST LAW OF THERMODYNAMICS

From the First Law of Thermodynamics for a closed system with no energy in the form of mechanical work crossing the system boundary we have;

$$E_{tot} = Q + \cancel{W} = \Delta U \tag{2}$$

- where E_{tot} = Total energy of the system
- Q = Energy in the form of heat
- W = Energy in the form of mechanical work
- ΔU = Change in internal energy

Assume the system is initially in equilibrium and contains saturated vapor and liquid. There will be an initial warm-up time required to bring the system to its new equilibrium operating condition once Q_{in} is applied. This warm-up time will be a

function of the thermal mass of the system. For this analysis assume the system has reached steady-state and that Q_{in} is a known value. It will also be assumed that the outside ambient T_a and the inside T_i temperatures are known.

HEAT TRANSFER MODE CONSIDERATIONS

Depending upon how Q_{in} is generated it is obvious that one must consider convection, conduction and radiation heat transfer modes. Due to the low temperatures in this application (70°F to 200°F), the author has elected to disregard the heat transferred by radiation since it is very small compared to the heat transferred by the other modes.

Q_{in} is force convected from the electronic packages within the enclosure up to the base of the vapor chamber. Depending on the internal air properties one can determine the external film coefficient h_i . Next, the heat is conducted through the evaporator base the rate of which is dependent upon the material geometry and properties.

Next, the heat is conducted from the evaporator base through the liquid layer where it will meet its next resistance to flow. This resistance manifests itself in the liquid surface to vapor interface. It is at this point where the liquid gives up its latent heat during its phase change to vapor. It is also at this interface where vapor molecules are recondensing back into the liquid.

The condensation rate at this liquid-vapor interface per unit area can be described by⁴;

$$r_c = ap \sqrt{\frac{M}{2\pi RT}} \quad (3)$$

where:

- r_c = Condensation rate per unit area
- a = Accomodation or sticking coefficient
- p = Vapor pressure
- M = Molecular weight
- R = Universal gas constant
- T = Absolute temperature of the vapor

The evaporation rate per unit area⁴, r_e , can be described by the same equation except that

T = Absolute temperature of the liquid

p = Equilibrium vapor pressure at temperature T :

If the vapor and liquid are at the same temperature and if the vapor pressure is identical to the equilibrium vapor pressure at that temperature then the evaporation and condensation rates are equivalent. However, if the liquid temperature exceeds the vapor temperature by dT and the vapor pressure exceeds the equilibrium vapor pressure by dp there will be a net mass transfer from the liquid surface to the vapor. This rate can be described as⁴;

$$r_e - r_c = ap\sqrt{M/2\pi RT} (dp/p - dT/2T) \quad (4)$$

Here, T can be taken as the liquid temperature and p as the equilibrium vapor pressure. It should be pointed out that equation (4) utilizes the usual kinetic gas theory assumption of a Maxwellian distribution of the gas molecules.

Now, one can determine the heat transfer rate by multiplying the mass transfer rate shown in equation (4) by the latent heat of vaporization for the liquid under study.

Thus far in the qualitative approach I have followed the heat transfer phenomena from its generation point inside the electronic enclosure to its latent heat vapor form inside the vapor chamber. The next event in the cycle would be the deposition of the vapor on the condensor and the subsequent phase change by which the latent heat of the vapor is given up. The condensation rate can be determined from equation (3). From a knowledge of heat of vaporization of the fluid one can determine the heat transfer rate. However, several physical complications occur at this vapor-liquid interface. For example, the probability that a given molecule contacts the cooler surface and sticks is difficult to obtain for a given fluid. This parameter is used in equation (3) and (4) as 'a' the accommodation coefficient⁴. This parameter depends not only on the fluid type⁴ but, also on the surface finish

condition of the condensor⁵.

CONDENSATION MECHANISMS

Specifically, condensation of a pure saturated vapor is exhibited by two mechanisms. One mechanism is referred to as "dropwise" condensation and the other is "film-type". On a rusty or etched plate the vapor will condense in a continuous film over the entire condensor plate. If the surface was smooth and polished the condensate will form in droplets which will grow in size rapidly⁵. It is also known that dropwise condensation can be brought about for a while by coating a surface with a petroleum based product, however, the condensate run off will soon wash this effect away⁵. It is obviously highly desirable to have condensation forming in droplets since at any instant of time a substantial portion of the condensing surface is free of condensate which allows the condensing process to continue at a high rate.

By utilizing the definition of viscosity and assuming that the velocity of the condensate on the condensor wall is zero and that the vapor molecules are at a maximum velocity at the liquid-vapor interface, theoretically, one can determine the thickness of the condensate film⁵. It is then possible to determine the local coefficient of heat transfer by assuming that the total thermal resistance lies in the condensate film. A more rigorous treatment of this subject can be referred to in reference 5.

The remaining portions of the vapor chamber heat transfer analysis lies in determining the heat transfer through the condensor plate to the outside ambient. These conditions are contingent upon the chamber material and the film coefficient on the outer wall.

APPARENT LIMITATION

The most important limitation on the rate at which heat can be transferred through the vapor chamber appears to be the rate at which the condensate can return to the evaporator. This would be somewhat analogous to the capillary pumping rate versus evaporation rate that is referred to in the heat pipe literature.^{2,3,4} For, if the evaporator burns out, the process fails.

As was pointed out earlier, the purpose of this chapter was to indicate through qualitative reasoning an approach to formulate a mathematical model of the vapor chamber system to predict the behavior.

CHAPTER III

ANALYSIS AND DESIGN OF A VAPOR CHAMBER

INTRODUCTION

In this chapter the physical parameters will be developed for a vapor chamber that will be applied to a specific electronic enclosure. Two prototype vapor chambers were constructed. The first prototype chamber performance was quite marginal. These shortcomings are pointed out in detail. A second prototype vapor chamber was built embodying those refinements necessary to improve the design of the first unit.

ANALYSIS OF THE ELECTRONIC ENCLOSURE

The analysis begins by determining the pressure drop balance. From this balance suitable vapor chamber parameters can be established. Even though this device behaves like a structure of high thermal conductance, it possesses heat transfer limitations established by the laws of fluid mechanics and the kinetic theory of gases. Some of the limitations are boiling rates, droplet formation and entrainment⁴.

If the amount of heat to be transferred is known, the physical enclosure limitations are known and the safe operating temperatures

are known the design procedure can begin.

For this application the enclosure mechanics are depicted in Figure 3. The overall height is 60 inches (152.4 cm.) with a width of 23 inches (58.42 cm.) and a depth of 38 inches (96.53 cm.). Inside this enclosure are electronic packages generating heat in the range of 1 to 2 kilowatts (3142 but/hr to 6284 btu/hr) depending on the specific control application. Refer to Chapter I page 2. The safe operating temperature inside the enclosure cannot exceed 132°F (55°C). The ambient temperature range is typically 75°F to 105°F (24°C to 41°C) in the majority of these operating control systems.

So as not to use internal enclosure space the vapor chamber will reside in the available space at the top of the enclosure, 19 inches by 34 inches by 6 inches (48.26 cm X 86.36 cm X 15.24 cm). This space availability, of course, dictates the maximum size of the chamber. Refer to Figure 3. Another reason for placing the vapor chamber here is to take advantage of any natural convection afforded by the conditions. The evaporator wall of the vapor chamber will in fact form the enclosure top so that it can be directly exposed to the internal enclosure environment. In order to keep the vapor chamber costs low it was decided not to increase the evaporator and condensor surface areas by adding fins. This decision, of course, does not prohibit adding fins to future designs if warranted. With the external size limitations

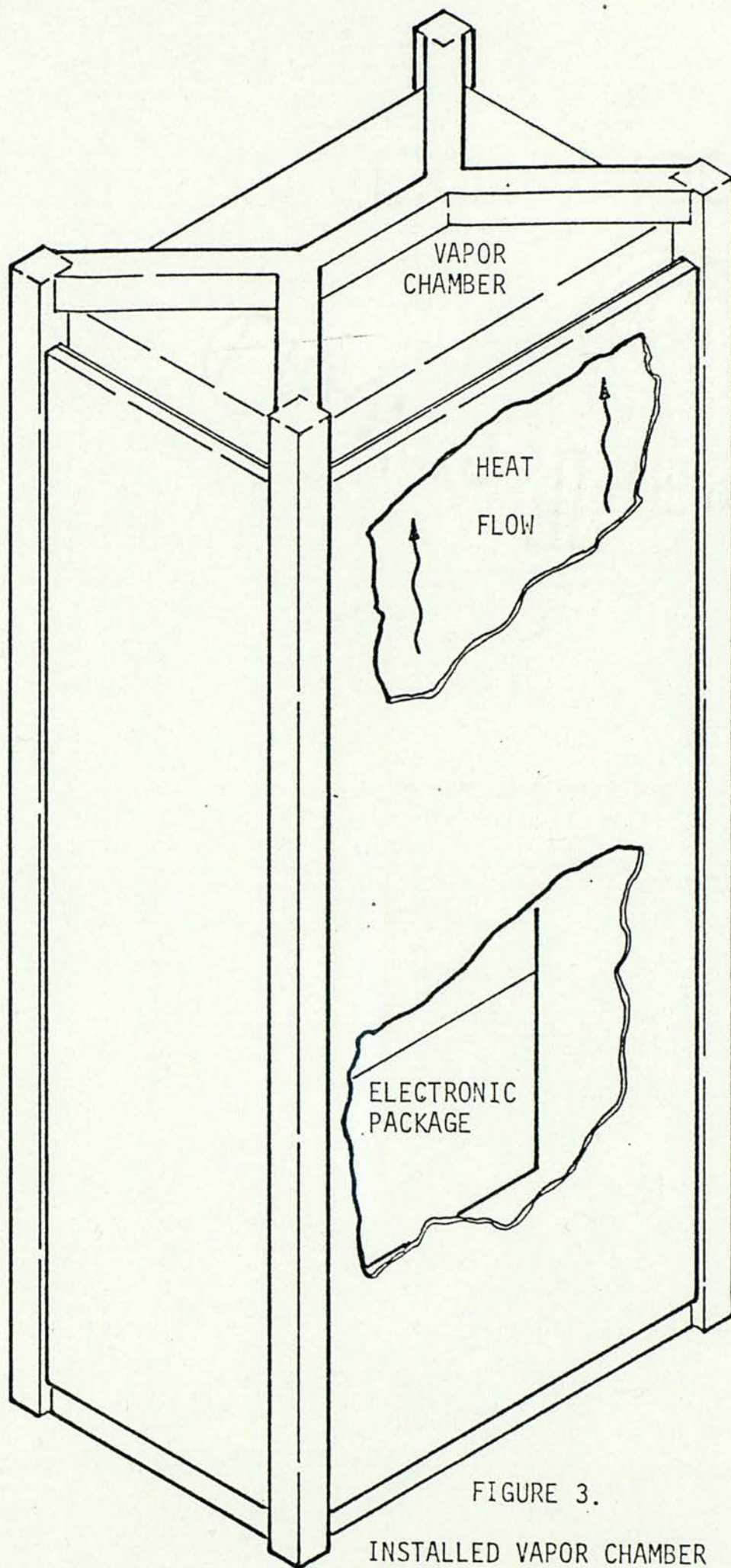


FIGURE 3.
INSTALLED VAPOR CHAMBER

determined, the working fluid and vapor chamber materials could be investigated.

WORKING FLUIDS

The vapor chamber operating temperature is dictated by the working fluid characteristics. Acceptable working fluid properties should include; high latent heat of vaporization, low viscosity, high surface tension, and should be compatible with the material of the vapor chamber^{2,3,4}. Some working fluids are shown in Table 1 that were researched by early heat pipe investigators^{6,7}. These investigators also conducted a study to determine what fluids would be compatible with a number of potential heat pipe envelope materials. A summary of this study is shown in Table 2. Water appears to have the most desirable characteristics in that it has the highest latent heat, high surface tension and low viscosity. However, from a knowledge of the thermodynamics of water it is known that at temperatures above 212°F (100°C) very high vapor pressures exist. Increasing the vapor chamber wall structure to account for this can only be done by paying higher cost penalties and lower thermal conductivity penalties. Reference to Table 2 also points out that in the presence of the materials surveyed that non-condensing gasses are formed when water is used except in the case of copper and nickel. Both Dowtherm-A and Dowtherm-E fluids have similar thermal capacities which results in performance approximately one-fourth that of water. Their flash points do present a

FLUID	BOILING POINT (1 ATM) ^{°F}	LATENT HEAT BTU/LB	SURFACE TENSION DYNES/CM	PRESSURE AT 450 ^{°F} PSIA	TOXIC	FLASH POINT ^{°F}	CRITICAL FLUX WATTS/IN ²
WATER	212	970	72	422	NO	NONE	703
FC-43	345	30	16	23	NO	NONE	70
DOWTHERM-E	352	119	37	51	SLIGHT	285	192
DOWTHERM-A	495	128	40	8	SLIGHT	255	172
CP-63	565	123	15	N/A	N/A	N/A	164
CP-9	567	121	15	N/A	N/A	N/A	162

(N/A = Data not presently available)

TABLE 1 FLUID PROPERTIES⁶

	H ₂ O	ACETONE	AMONIA	METHONOL	DOWTHERM-A	DOWTHERM-E	FREON-113
COPPER	RU	RU	NR	RU	RU	RU	UK
ALUMINUM	GNC	RL	RU	NR	UK	NR	RU
STAINLESS STEEL	GNT	PC	RU	GNT	RU	RU	UK
NICKLE	PC	PC	RU	RL	RU	RL	UK

RU = Recommended by past successful usage

RL = Recommended by literature

NR = Not recommended

UK = Unknown

GNC = Generates noncondensable gas at all temperatures

GNT = Generates noncondensable gas at high temperatures when oxide is present

PC = Probably compatable

TABLE 2 COMPATABILITY OF WORKING FLUIDS AND CHAMBER MATERIALS⁷

Potential fire hazard. It is also unknown according to the compatibility study shown in Table 2 whether or not Dowtherm-A is compatible with aluminum. According to Dow Chemical Company⁸, Dowtherm-A has very low vapor pressure at the temperatures in the range of 75°F to 132°F. These vapor pressures are on the order of .001 to .005 psia. A particular reason for avoiding low vapor pressures is that small amounts of air or other non-condensable gases in the vapor chamber are most likely to interfere with the heat transfer process⁴. According to Reference 4, other suitable liquids that might be considered for this temperature range would be the Freons. Further investigation resulted in locating trichlorotrifluoroethane (FR-113) which has a boiling point of 117.6°F at 0 psig or 14.7 psia. The complete Thermodynamic Properties of FR-113 are given in Appendix A. Fr-113 is non-combustible and non-flammable (Underwriters' Laboratories Report MH3072, page 16) and much less toxic than Group 4 Classification (Same report, page 14). Using this fluid with a suitable vapor chamber material will allow steady-state operation at a minimal pressure condition thus alleviating the need to meet Boiler and Pressure Vessel Codes.

The latent heat of vaporization 117.6°F, 0 psig is approximately 63.09 btu/lb. and the heat content of the vapor is approximately 96.12 btu/lb. The viscosities of the vapor phase and the liquid phase conditions are approximately 0.0108 centipoise

and 0.497 centipoise respectively. These properties compare favorably with previously mentioned working fluid requirements given on page 18 and shown in Table 1.

VAPOR CHAMBER MATERIALS

Depending on the operating state point of the system, the vapor chamber can sometimes be subjected to high internal pressures, as well as, be an integral structural member of a system. It is for these reasons that the chamber material should possess strength and compatibility with the fluid and the enclosure. The material selected must be readily available, possess the necessary properties to withstand the operating pressures of the fluid vapor, lend itself to standard manufacturing processes, exhibit high thermal conductivity, and be compatible with the selected working fluid. Of the materials shown in Table 3⁷ copper is the best choice due to its high thermal conductivity, however, this material has a tendency to corrode in its natural state when subjected to hostile environments and its performance may deteriorate plus its cost per pound is relatively high compared to the other materials. Aluminum has a thermal conductivity higher than stainless steel and is also known to be easier to machine and form. On a cost basis aluminum and stainless steel compare favorably. For these reasons 6061 annealed aluminum was selected.

The freon family and aluminum are indeed compatible as is

Material	Condition	Thermal Conductivity	Yield Stress	Density	Specific Heat	Cost Per Pound
		$\frac{\text{Btu-ft}}{\text{hr-ft}^2-\text{°F}}$	Psi	10^{-2} lb/in ³	10^{-2} Btu/lb ^{°F}	\$ ¹⁰
Aluminum	T-6 Annealed	.99	40 8	9.8	23	1.17
Copper (OHFC)	Hard Annealed	226	40 10	32.3	9.2	1.88
Stainless Steel (304)	Hard Annealed	9.4	75 35	29	12	1.24
Monel (K-500)	Hard Annealed	10.1	90 40	32	10	8.05

TABLE 3. VAPOR CHAMBER MATERIALS^{7,10}

evidenced in their heavy uses in air conditioning systems where aluminum parts are continually subjected to freom fluid-vapor contact. It was assumed the strength of aluminum would be satisfactory since the steady-state operating point of FR-113 is 0 psig or below. This assumption was not adequate after completion and preliminary testing of the initial vapor chamber. This matter is discussed further in the later portion of this chapter.

FIRST PROTOTYPE VAPOR CHAMBER

Based upon the foregoing investigation the first test chamber was designed and constructed. The structure is shown in Figure 4. Note should be taken of the diagonal creases on the upper and lower surfaces. Their purpose is twofold. First, it inherently strengthens the chamber and secondly it promotes increased efficiency in the return flow of the condensate much in the same manner as stalactites that are found in underground caves. Although the natural finish of 6061 aluminum is not polished, it can be considered smooth for all practical purposes. This is a desirable characteristic for the promotion of drop-wise condensation as was pointed out in the earlier discussion beginning on page 13 of this chapter.

PERFORMANCE CHARACTERISTICS OF THE FIRST VAPOR CHAMBER

The performance characteristics of the first vapor chamber

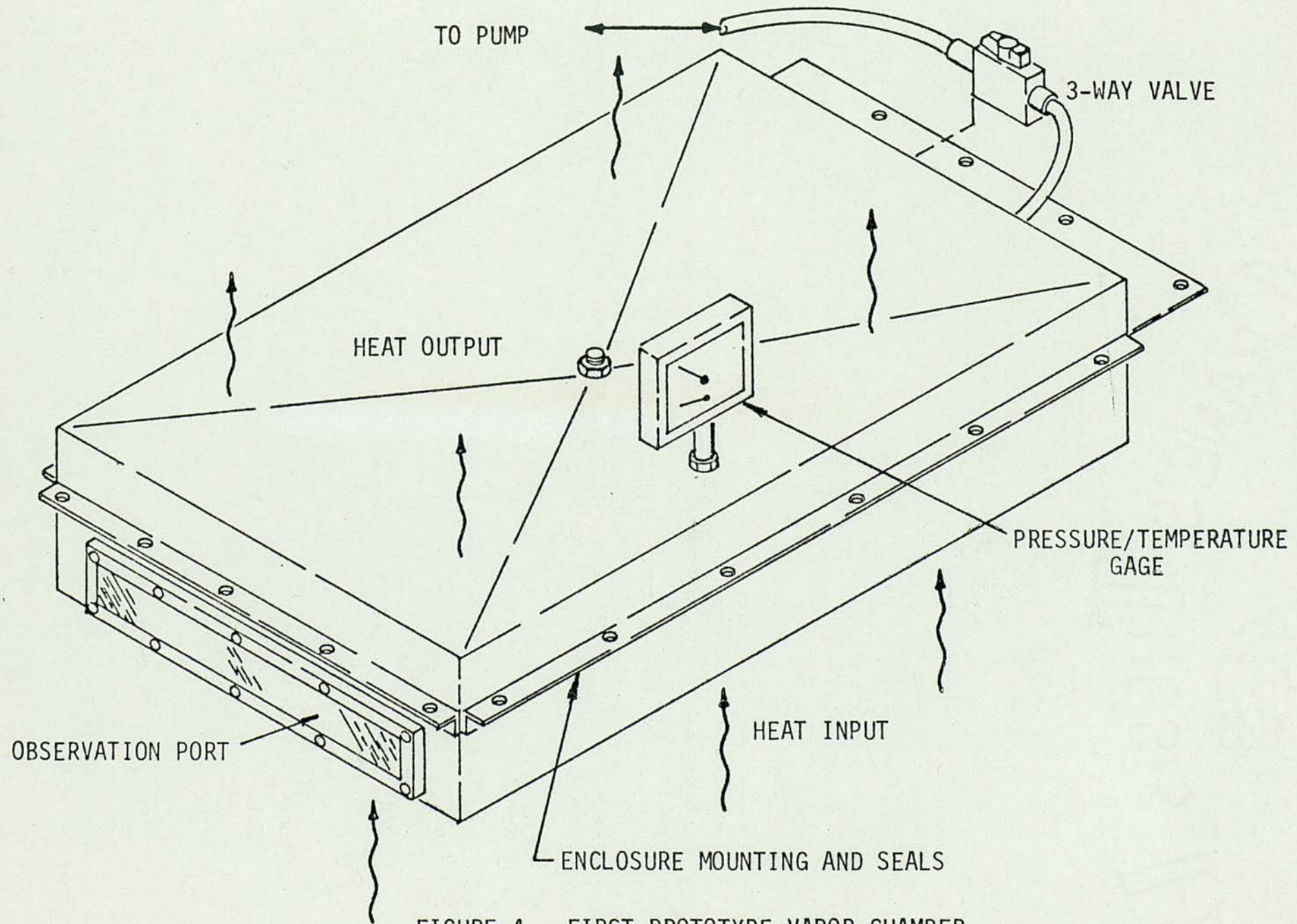


FIGURE 4. FIRST PROTOTYPE VAPOR CHAMBER

design were less than satisfactory for the following reasons.

The observation ports required numerous mechanical fasteners and gaskets. This requirement made it impossible to obtain a total seal in the chamber.

When the chamber was evacuated prior to operation, the condensor and evaporator deformed considerably even when a stiffening post was placed in the center. This deformation resulted in a non-uniform liquid level over the evaporator which in turn made for non-uniform evaporation when heat was subjected to the chamber base.

When the chamber reached the state point where the internal pressure was 0 psig, it became apparent that the apparatus had to be leveled in order to insure a uniform liquid layer over the evaporator. This leveling requirement may be difficult to achieve in a real system.

One gallon of Freon 113 was placed in the chamber. The working fluid along with the material of the chamber required a warm-up time of 30 minutes before reaching equilibrium. This amount of time could be detrimental to a real system.

Even in light of these shortcomings some positive results were obtained.

During one test run, the following conditions existed. The room temperature was 75°F, the internal enclosure temperature

stabilized at 135°F with a known heat input of 1600 watts (5460 btu/hr).

The overall heat transfer coefficient was calculated to be¹¹:

$$U = \frac{Q}{A(T_i - T_o)} = 20.6 \frac{\text{btu}}{\text{ft}^2 \cdot ^\circ\text{F}} \quad (5)$$

Where U = Overall heat transfer coefficient

Q = Heat load (btu/hr)

A = Surface area (ft²)

T_i = Inside cabinet temperature (°F)

T_o = Room ambient temperature (°F)

The vapor was observed to condense readily on the creased roof structure in the form of droplets and return at a steady rate via the creases and center support post to the evaporator.

Due to the minimal success gained on the first chamber model the author decided to build a second embodying what was learned from the first.

SECOND PROTOTYPE VAPOR CHAMBER

The same working fluid and chamber material were used, however, a smaller amount of fluid to lower to lower the warm-up time was considered and the mechanical package of the vapor chamber turned out to be substantially different. The same external dimensions were used in the second chamber unit with the exception

of the height. It was reduced to two inches. There appeared to be no advantage gained from the first unit which was five inches high except to provide suitable space for the observation ports. In the first model the condensate collection and return appeared to be sufficient, hence, there was no further need for the observation ports with their inherent sealing problems.

The problems associated with the deflection of the evaporator and the condenser plates were eliminated by placing an aluminum grid work inside the chamber. Assuming simply supported plate grid sections, the optimum spacing was obtained from¹²

$$\max y = \alpha \frac{wb^4}{Et^3} \quad (6)$$

where y = Maximum deflection at the center

α = Shape factor

w = Load

b = Grid spacing

E = Modulus of elasticity

t = Plate thickness

A uniform load of 20 pounds per square inch would obtain a maximum deflection of .006 inches with a plate .062 inches thick. This grid space worked out to be approximately 2 inches by 2 inches. See Figure 5 for the resulting second design. In order to insure that the vapor circulates as freely as possible

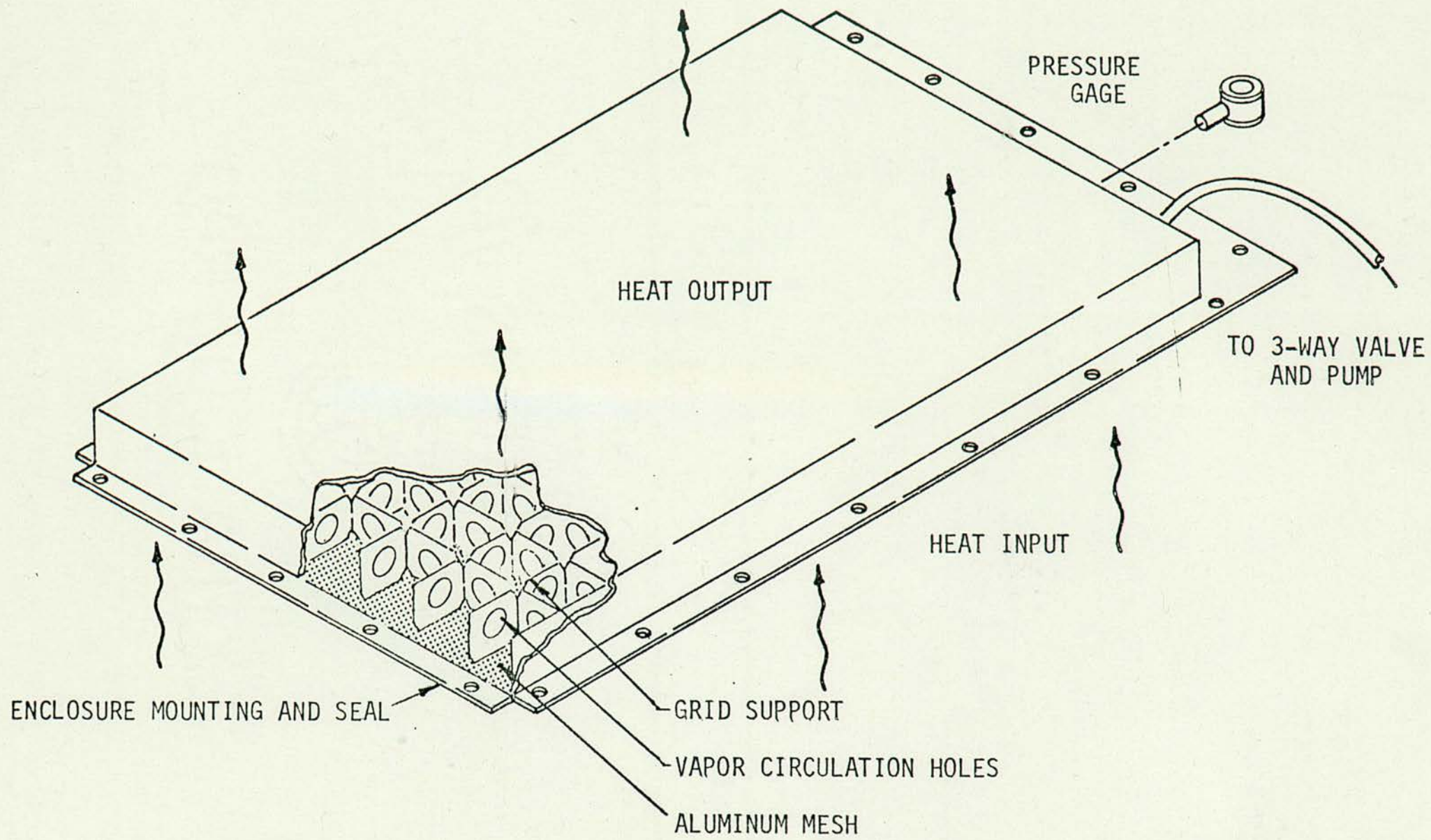


FIGURE 5. SECOND PROTOTYPE VAPOR CHAMBER

throughout the grid pattern, holes were strategically placed as shown in Figure 5. With this gridwork it became obvious that the fluid level in a given cell could burn out depending on how the input heat load was applied to the bottom of the evaporator. To prevent this from occurring, it was decided to place several layers of mesh aluminum screen wire between the grid supports and the evaporator plate. Refer to Figure 5.

ALUMINUM MESH CONSIDERATIONS

The mesh had to be designed to contain sufficient working fluid to operate satisfactorily for the intended heat load. This problem was solved by early heat pipe investigators and found to be⁶:

$$t_w = \frac{Q l_d \nu}{\gamma 4 L l_w r_c C_r} \quad (7)$$

where

- t_w = Screen thickness (inch)
- Q = Heat load (btu/hr)
- l_d = Distance between hot spots (inch)
- L = Latent heat of vaporization (btu/lb)
- l_w = Width of hot spots (inch)
- γ = Surface tension (lbs/hr²)
- ν = Kinematic viscosity (ft²/hr)
- r_c = Pore size (inch)

C_r = Capillary conductance

Reference 3 points out that this last term, C_r , is really a dimensionless ratio of (ϵ/b) where ϵ is defined as the wick porosity and b is a dimensionless geometrical factor that has approximate values of 8 for parallel non-connected cylindrical pores, and lies between 10 and 20 for realistic capillary structures with interconnected pores.

It turned out that this aluminum mesh solved another problem inherent in the first design. That is, a saturated mesh screen no longer required the evaporator to be precisely leveled in order to insure uniform liquid levels. The capillary pumping action provided by the screen insured that if burn-out did occur, working fluid would replenish that section.

It should be noted in passing that adding the aluminum mesh and the grid work complicates the mathematical model discussed in Chapter II. It was also discovered that during trials of the first prototype vapor chamber, no steps were taken to minimize any water vapor content that may be present in the chamber prior to operating. Conversations with heat transfer specialists pointed out that a 5% water vapor content can lower the heat transfer rate by as much as 50% in systems of this kind.¹³

FILLING PROCEDURE

In order to circumvent this possibility the following

procedure was established. First an inert gas was introduced into the chamber to purge out as much water vapor as possible. Bottled nitrogen gas was utilized for this purpose. The vapor chamber was then evacuated with a vacuum pump. This vacuum in the chamber was utilized to introduce one quart of Freon 113. This amount of working fluid was sufficient to saturate the aluminum screen mesh. Finally, the vapor chamber was again evacuated to the state point required to start the trial runs.

TEST EQUIPMENT FOR THE FIRST VAPOR CHAMBER

The cost to instrument and measure the interface conditions inside the vapor chamber became too prohibitive. Hence, a multiple gage was mounted on the vapor chamber top of the first design to monitor gage pressure and temperature of the vapor. A three-way valve was installed to allow alteration of the beginning state point of the fluid via pumps. Refer to Figure 4. Suitable temperature probes were also placed inside the enclosure and on the vapor chamber top.

A heat source capable of 1600 watts (5460 Btu/Hr) continuous input was placed in the bottom of the electronic enclosure. With these known values including the outside and inside temperatures plus the vapor chamber geometry, the overall heat transfer coefficient could be determined from Equation (5) in this chapter.

TEST EQUIPMENT FOR THE SECOND VAPOR CHAMBER

It was felt that the measuring equipment used on the first vapor chamber was not adequate to measure the vapor pressure in that the multiple gage was only readable to + or - 2-1/2 psia. The following equipment and calibration procedure were used.

1. Statham Lab 0-15psia Pressure Transducer Model P96-15A-400
2. Digital Voltmeter. Triplet Model 8000
3. Trygon D.C. Power Supply. Model HR40-5B
4. U-Tube Manometer, Central Scientific Co. Model 44125
5. Vacuum Pump. Bendix Part Number 4-17125

CALIBRATION PROCEDURE

The above equipment was hooked up as is indicated in Figure 6. The excitation voltages used on the pressure transducer was 14 VDC. The digital voltmeter indicated 50 millivolts when measuring one atmosphere. The U-tube manometer indicated equal legs of 515 mm Hg when measuring one atmosphere.

For a U-tube manometer, the pressure relation is given by¹⁴

$$P - P_a = h(\rho_{hg} - \rho_a) \quad (7)$$

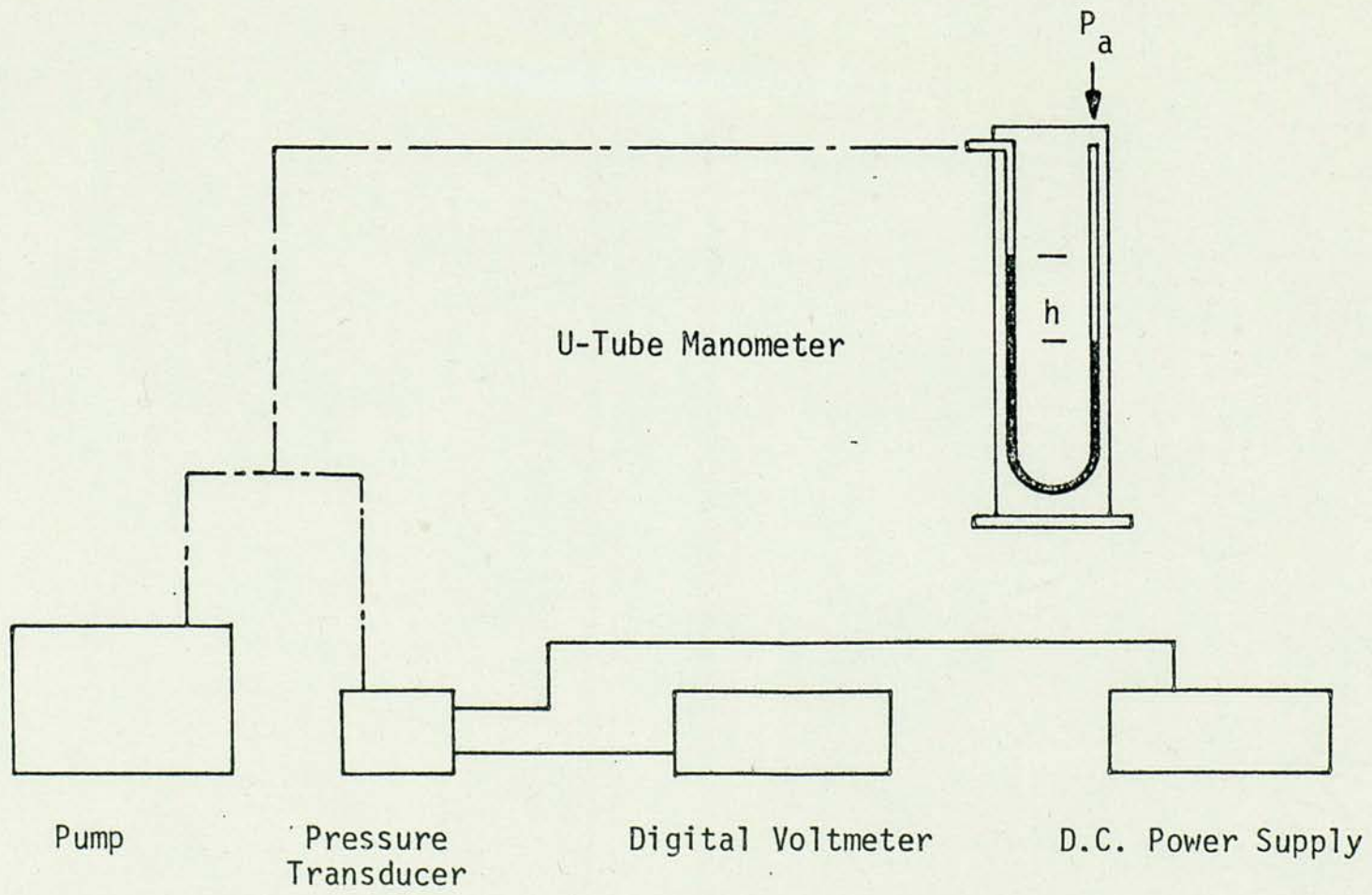


FIGURE 6. PRESSURE TRANSDUCER CALIBRATION SET UP

where P = Unknown pressure (psia).
 P_a = Atmospheric pressure (psia)
 ρ_{Hg} = Density of mercury (lb/ft³)
 ρ_a = Density of air (lb/ft³)
 h = Differential column height of mercury. (inch)

The vacuum pump was turned on and adjusted to several pressure settings via a valve. At each of these settings the differential column of mercury was recorded along with a reading in millivolts sensed by the digital volt meter. The unknown pressure was calculated by using Equation (7) for each of 6 points. This data is tabulated in Table 4 shown below. The corresponding pressure curve versus millivolt readings are shown on Figure 7.

h mm-Hg	h inch	P psia	Voltage millivolts
0	0	14.70	50.00
57	2.24	13.60	44.50
91	3.58	12.95	41.40
291	11.46	9.08	28.80
392	15.43	7.14	21.80
491	19.33	5.23	15.50

TABLE 4. CALIBRATION POINTS

ABSOLUTE PRESSURE
VS.
TRANSDUCER VOLTAGE

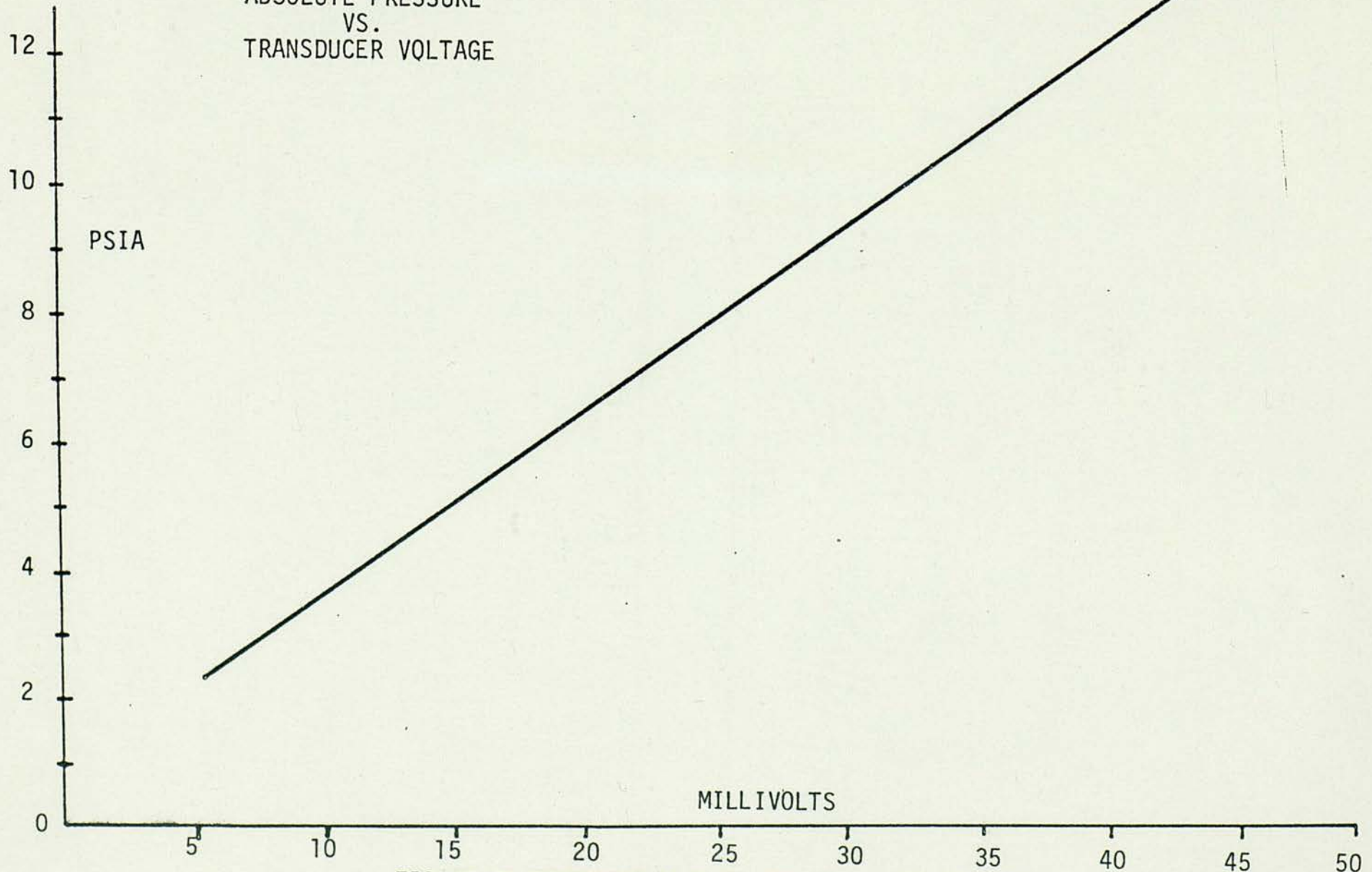


FIGURE 7. PRESSURE TRANSDUCER CALIBRATION CURVE

The maximum pressure that the transducer could be subjected to was 15 psia. Care had to be exercised when conditions of the test runs brought the pressure close to one atmosphere.

CHAPTER IV

PERFORMANCE CHARACTERISTICS OF THE VAPOR CHAMBER

INTRODUCTION

In this chapter the operating characteristics of the vapor chamber will be presented. The second chamber was constructed and installed in the equipment enclosure as shown in Figure 3 page 17. A series of heat test runs were completed. It was felt that the performance could be best measured by comparing the steady-state temperature difference between room ambient and the internal enclosure with the vapor chamber installed versus the same enclosure with a normal top.

FIRST HEAT TEST RUN

Insulated foam board walls were used instead of the normal steel walls on the equipment enclosure. The insulated walls minimized the conductive heat losses so that the effects of the vapor chamber could be better evaluated. The internal cabinet temperature rate increase (dT_i/dt) with the input heat load of 1600 watts (5460 Btu/Hr) proved to be too much for the vapor chamber. The Freon 113 became super heated and the resulting

vapor pressure deformed the condenser and evaporator walls of the chamber. Leaks resulted due to cracked welds. The minute cracks that were propagated from the overpressurization proved to be difficult to find. The overpressure condition put a permanent set in the evaporator and condenser plates. Also, some of the internal aluminum grid-work was deformed. The vapor chamber had to be cut open and some of the grid plates had to be replaced. Figure 8 shows that the cabinet temperature climbed very rapidly to approximately 212°F. Due to the vapor chamber deformation the first series of test runs were halted. It was not determined in this test what the ultimate equilibrium condition would be. The temperature was certainly much higher than was reached by the first chamber design under similar conditions. The warm-up time was noted to be considerably faster than the first chamber. The reason for this appears to be the reduced mass of the second vapor chamber design.

The high temperature reached in this first test may have been due to several reasons. One, there may have been insufficient fluid in the chamber and it boiled off faster than the condensate could be returned to the evaporator. Secondly, there may have been some water vapor or other non-condensable gasses prohibiting the heat transfer in the vapor chamber. Lastly, the deformation of the chamber as the vapor pressure exceeded one atmosphere may have resulted in separating the aluminum screen mesh from

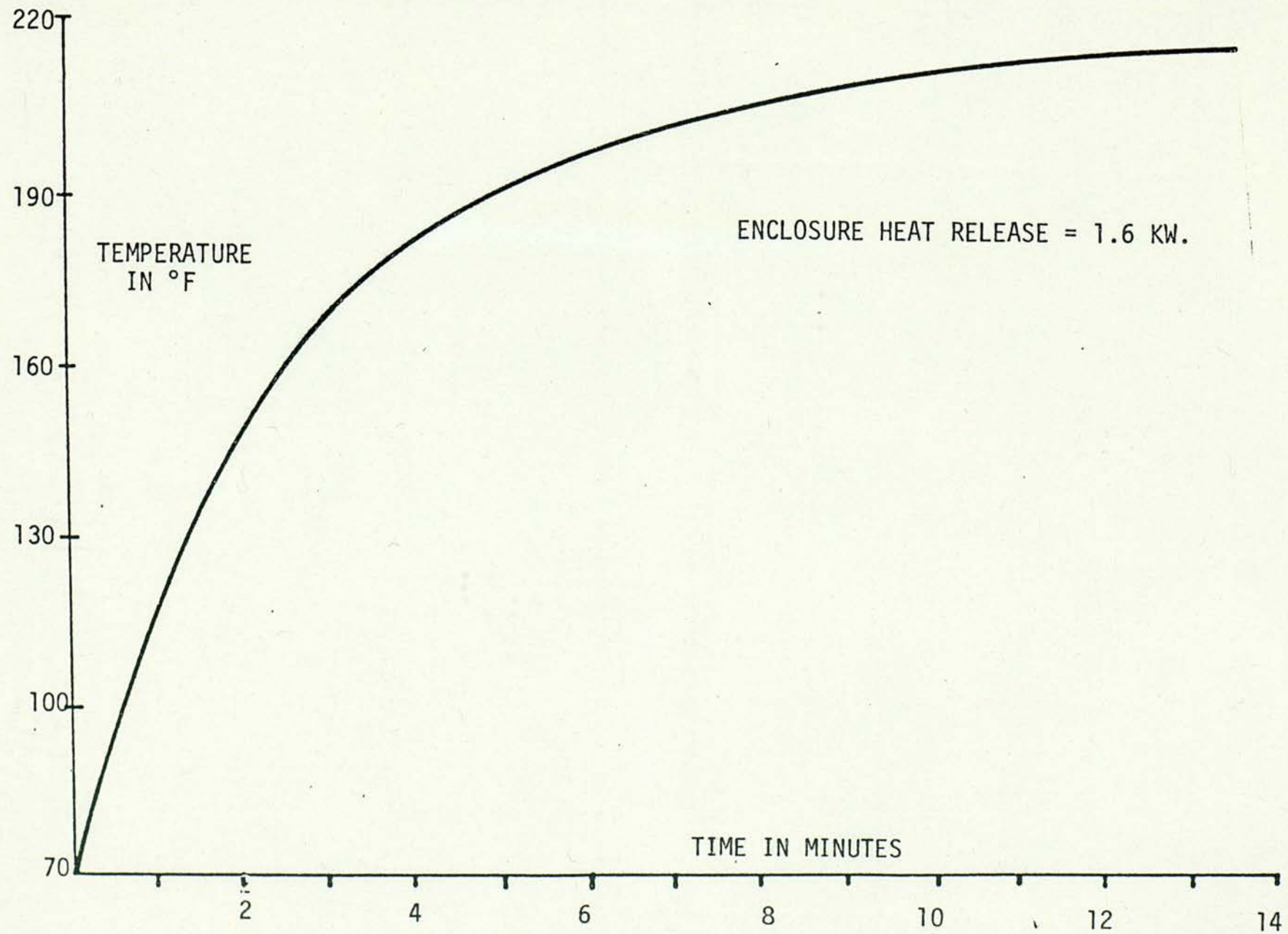


FIGURE 8. THERMAL RATE CURVE NO. 1

the evaporator increasing the thermal resistance.

When the vapor chamber was opened for repairs the following was noted. Some water drops were observed to be clinging to the screen mesh. Some of the grid-work plates were deformed and the screen was separated from the evaporator. The defective parts were replaced and the vapor chamber was welded closed.

SECOND HEAT TEST RUN

Prior to making the second heat test, the vapor chamber was purged for 30 minutes with nitrogen gas to alleviate as much water vapor as possible that may have been present. Next, the chamber was evacuated to 2 psia and left untouched for 48 hours to insure no leaks were present. One quart of Freon 113 was introduced into the chamber and then evacuated to 2 psia for 24 hours. During this test run the heat source was cycled on and off to insure that the thermal shock would not repeat the chamber damage observed in the first test run. The temperature/time graph is shown on Figure 9. It is interesting to note that the equilibrium cabinet air temperature is substantially lower than that observed on the first test run. If the vapor chamber had withstood the dT/dt of the first heat test it may have stabilized to this temperature.

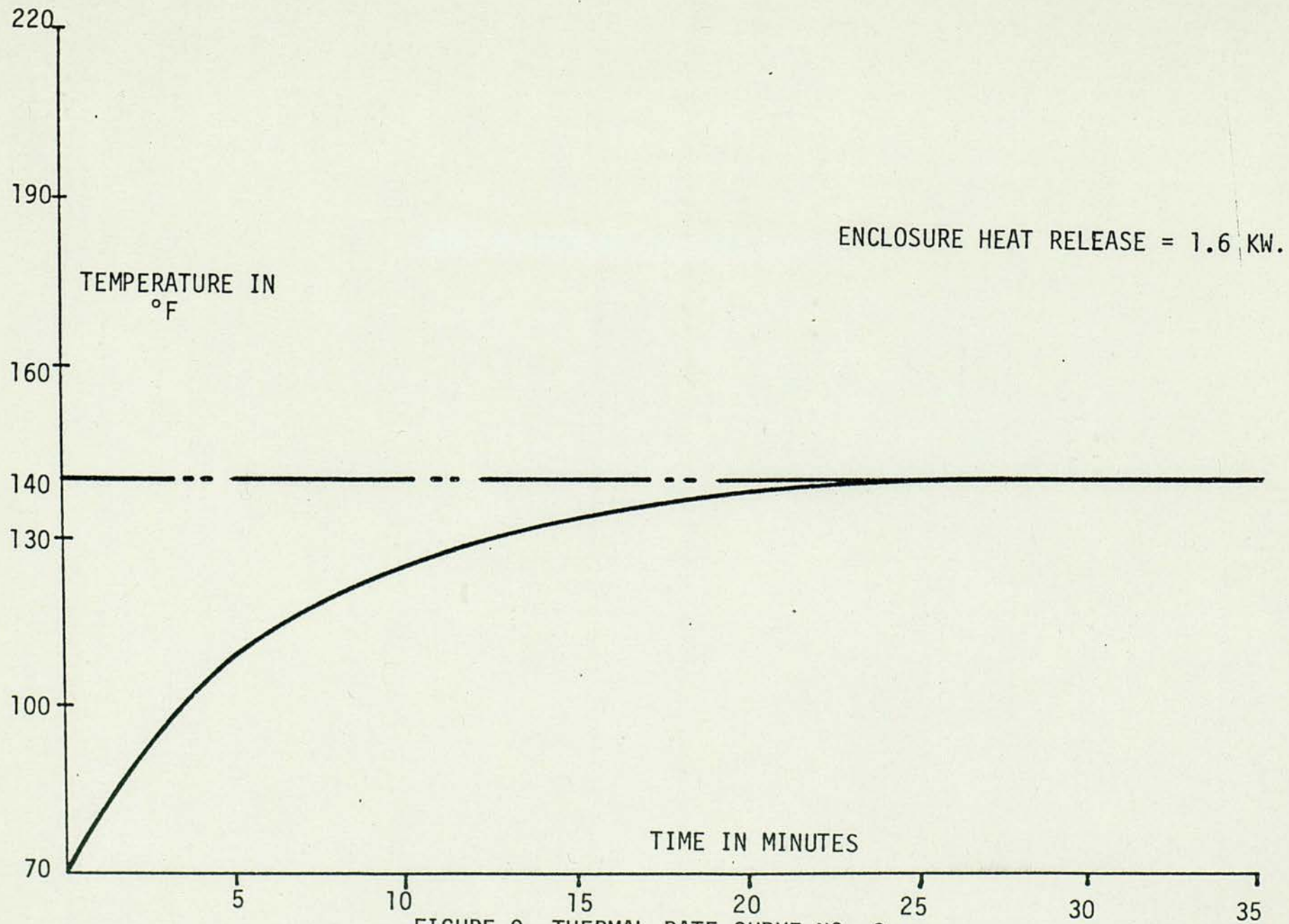


FIGURE 9. THERMAL RATE CURVE NO. 2

THIRD HEAT TEST RUN

In the concluding heat test run, the following changes were made to the test enclosure. First, the vapor chamber was removed and replaced by the normal top. This top was made from low carbon steel (1018) and had a polyurethane painted surface. Secondly, no attempt to lower the temperature rate of the enclosure was attempted. Figure 10 shows the results of this test run. Note should be taken of the time required to reach the equilibrium temperature of 170°F.

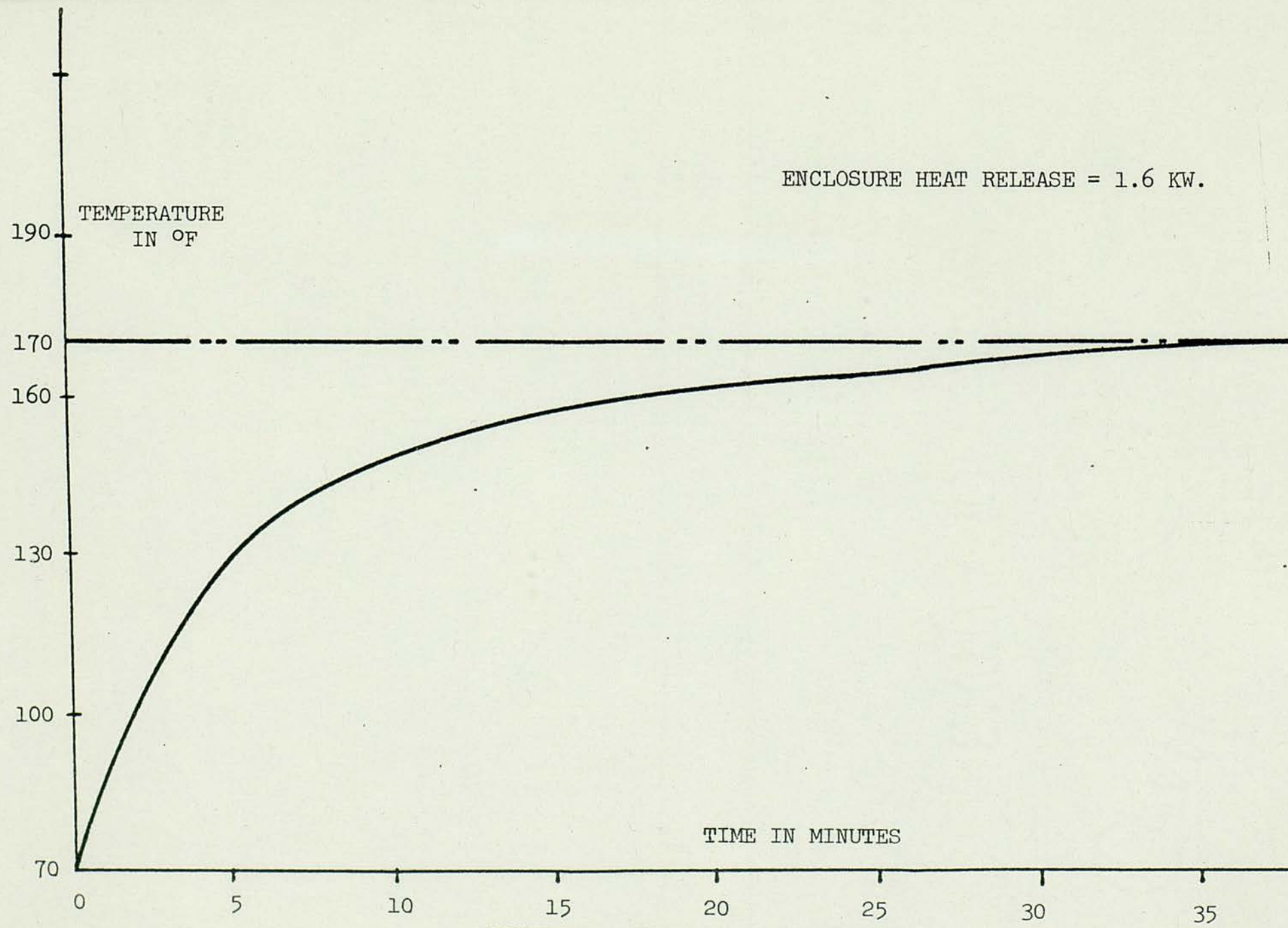


FIGURE 10. THERMAL RATE CURVE NO. 3

CHAPTER V

RESULTS AND CONCLUSIONS

INTRODUCTION

It was concluded from the results outlined in Chapter IV that a heat exchanging device capable of operating effectively over a given temperature as might be experienced in a hostile environment as described in Chapter I is indeed feasible. Further, it can be made to meet the desired design characteristics as described on page 4 of Chapter I. These characteristics are repeated and discussed below.

VAPOR CHAMBER DESIGN CRITERIA

1. The device should be able to work in conjunction with a sealed enclosure such as NEMA-12.

The electronic enclosure that the vapor chamber was tested on falls into the category of NEMA-12 rating when proper seals are applied at the wall and door joints.

2. If the device requires prime movers it would be desirable that they do not add to the heat load of the enclosure.

No prime movers were used in this particular application. It may be required to add an internal blower of some kind as well as an external blower to increase the heat transfer rate. This

point will be discussed further in this chapter.

3. It would be highly desirable that the device require a minimum of enclosure volume.

The vapor chamber was placed on the electronic enclosure top which required no internal volume.

4. The device should be applicable to a variety of enclosure designs without requiring major changes.

It should be obvious to the reader that the simplicity of the vapor chamber design can be readily applied to most existing enclosure designs by simply fabricating the unit larger or smaller.

5. The device should operate under a closed system not requiring external supply lines.

The vapor chamber is indeed a closed system not requiring external supply lines.

6. The device should be able to transfer high heat rates when small temperature differences exist between internal and ambient operating conditions.

The heat load used in these tests on the vapor chamber resulted in a temperature difference of approximately 70°F. For this particular application, this is unsatisfactory since the safe operating temperature was specified as 132°F for the electronic packages in the enclosure. This point will be discussed further in this chapter.

7. The device should be able to be manufactured in a cost effective manner.

Preliminary cost data accumulated for the vapor chamber was \$70.00. A 350 cfm base blower currently used to cool this enclosure cost \$95.00. This of course does not include the cost of the vertical space of the enclosure housing the blower. Based upon this preliminary data the vapor chamber appears to be cost effective.

ADDITIONAL RESULTS

A comparison of Figures 9 and 10 in Chapter IV shows that the vapor chamber under the heat load conditions pointed out actually resulted in the enclosure air temperature to be 30°F lower than when the normal equipment enclosure top was in place.

CONCLUSIONS

It was pointed out earlier that heat pipes are capable of transferring heat at rates several orders of magnitudes greater than the best solid conductors of the same dimensions. In the tests performed comparing the vapor chamber installed and removed the only thing that could be concluded was that the vapor chamber performed better than the steel enclosure top when both were subjected to natural convection cooling to and from their external surfaces.

It seems reasonable to conclude that the performance of

the vapor chamber could be improved by increasing the surface area of both the evaporator and condenser. It also seems reasonable to expect further performance enhancements by adding external and internal blowers to force convect the heat to and from the vapor chamber.

HEAT PIPE HEAT EXCHANGER¹⁵

A new product called a Heat Pipe-Heat Exchanger has been developed by McLean Engineering Laboratories. The unit is 40-1/4 inches long by 16-1/2 inches wide by 8 inches deep, and consists of a bank of heat pipes and two dual centrifugal blowers. It is mounted on the door or mounting rails of an electronic rack and does not take up any interior cabinet space. Cabinet air is cooled and recirculated without introducing any outside contaminant. A dual centrifugal blower mounted in the bottom of the unit draws the hot cabinet air through the bottom half of the heat pipe bank, thus cooling it, and discharges this cool air into the cabinet at the rate of 350 CFM at 0" S.P. A similar dual centrifugal blower mounted in the top of the unit draws ambient air through the top half of the heat pipe bank, which in turn removes the heat from the heat pipes, and discharges this heated air to the atmosphere. Figure 11 shows the performance curve of this unit under conditions of no blower, bottom blower only, and both blowers operating. It is interesting to note

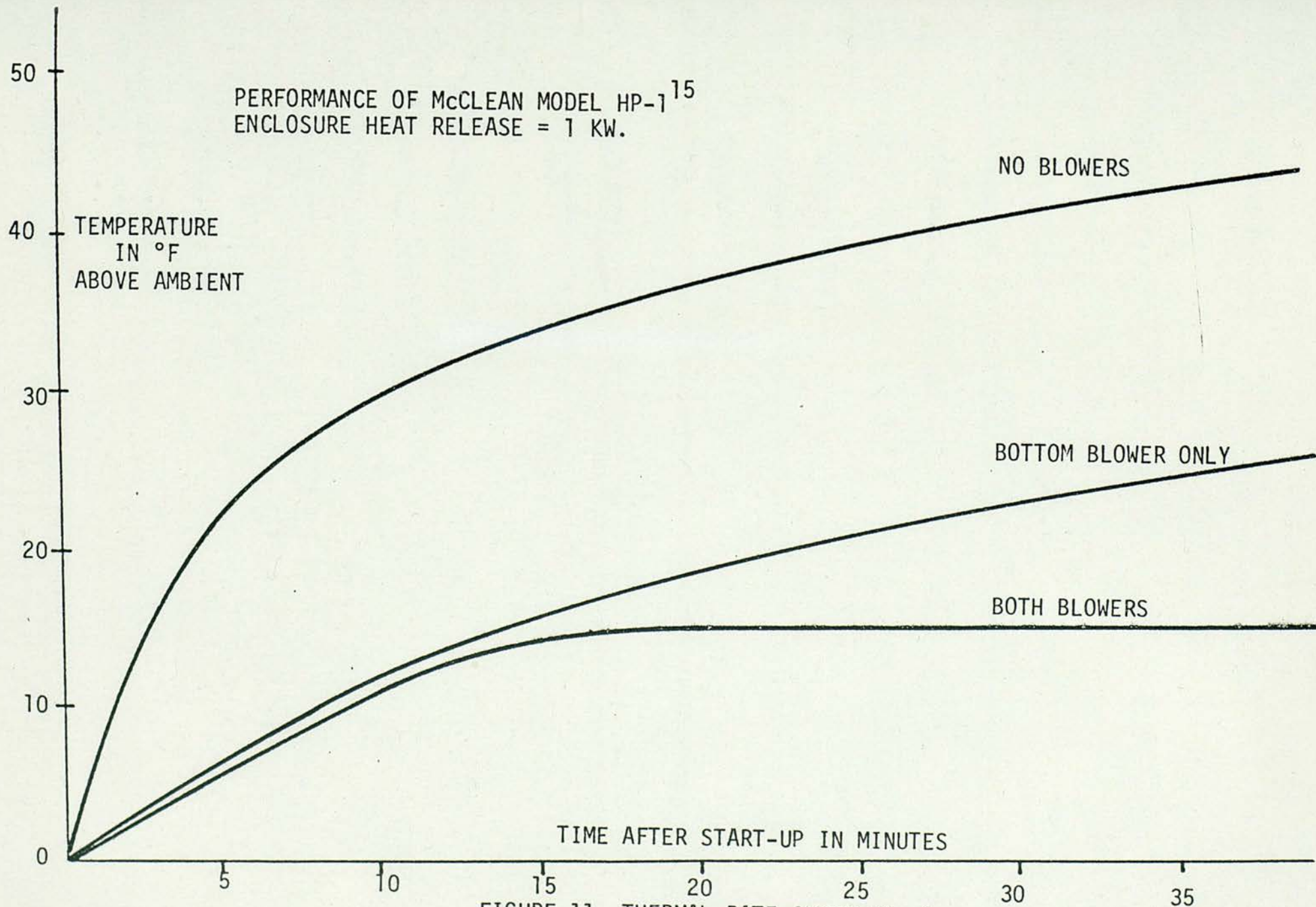


FIGURE 11. THERMAL RATE CURVE NO. 4

that the McClean unit operating under the conditions of no blowers shows that the enclosure temperature rises to approximately 45°F above ambient. Note should be taken that their tests were based upon using a heat load of 1000 watts as compared with 1600 watts used on the vapor chamber tests.

The McClean heat exchanger employs copper heat pipes using water as the working fluid. The reader will recall that the working fluid used in the vapor chamber, Freon 113, had a latent heat of vaporization many times lower than that of water. The results obtained from McClean Laboratories further strengthens the author's conclusions as to what effect the blowers and increased surface area of the condensor and evaporator may have on the performance of the vapor chamber. It also strengthens the viability of the vapor chamber as a device for cooling electronic enclosure in hostile environments.

These results showed enough promise that a patent search was propagated by Westinghouse Electric Corporation. The search which resulted showed no activity of a device such as this being applied for enclosure cooling. A patent was formally written and filed. A copy of this document is contained in Appendix B. At this writing, the patent on the vapor chamber is pending.

FURTHER STUDY

It would be premature to release this concept for manufacturing

before more study and tests can be performed. For example, the tests were performed on the vapor chamber at sea level conditions. A vapor chamber operating at higher altitudes may not perform the same. More tests need to be run in order to determine the transient warm-up time. In some instances expensive equipment could be destroyed if they are overheated before the vapor chamber can respond properly.

DOWTHERM A

Late in the investigation of the vapor chamber it was learned from Dow Chemical Company that Dowtherm-A is indeed compatible with aluminum. It would be highly desirable to run further tests on the vapor chamber using Dowtherm-A since this particular working fluid has a latent heat of vaporization approximately three times as great as Freon 113⁸. The fluid is undesirable due to its flash point and toxicity, however, since only small amounts of the fluid are required in the vapor chamber it may turn out to be a more suitable working fluid.

COMPUTER MATH MODEL

A math model of the operating vapor chamber in the form of a computer program is needed to accurately predict the design parameters needed to match a vapor chamber to a known set or required working conditions. This will minimize the engineering costs on new applications. A good starting point for such a program

would be the programs developed on heat pipes shown in detail in Reference 3.

PRESSURE BUFFER

Further investigation needs to be done on a device to take care of those instances when superheated vapor is present causing high vapor pressures and subsequent structural damage to the vapor chamber. One consideration would be to attach some sort of a bellows that would be in contact with the vapor whose function would be to accommodate the high vapor pressure experienced during the warm-up period of a system.

CASCADED VAPOR CHAMBERS

Another application of this concept could be to cascade several vapor chambers in series each programmed to operate at different state points. This could be readily applied to a control system containing packages that can only be operate safely at different temperatures. A good example of this would be a mass-memory storage device such as a moving head disk. This piece of equipment has a safe operating upper temperature of 90°F. It is conceivable that the moving head disk could be placed in the same equipment enclosure housing a computer which operates at an upper temperature of 132°F. A small vapor chamber could be placed on the top of the moving head disk. This disk would

in turn be placed below the computer electronic package. The small vapor chamber would allow the moving head disk to operate safely at 90°F and a second chamber on the enclosure as described in this thesis would allow the system to operate safely. The net result being that the system containing the packages of varying sensitivity could realistically be operated at higher net temperatures.

VAPOR CHAMBER AIDED BY HEAT PIPES

A final application worthy of further study would be to consider using heat pipes in conjunction with a vapor chamber as described in this thesis. Heat pipes could be used to bring the heat from localized hot spots within a given electronic package to the vapor chamber which is placed on the enclosure. The obvious advantage of a system comprised of these elements would be the elimination of small fans and blowers that are currently used to cool localized hot spots in electronic packages. These small fans and blowers are a constant maintenance problem as well as heat additions to the overall enclosure.

APPENDIX

APPENDIX A. The Thermodynamic Properties Of Freon 113..... 55

APPENDIX B. Patent Application Copy Filed For A Vapor
Chamber..... 66

Thermodynamic Properties
of
"FREON" 113
TRICHLOROTRIFLUOROETHANE
 $\text{CCl}_2\text{F}-\text{CClF}_2$
With Addition
of
Other Physical Properties

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THE THERMODYNAMIC PROPERTIES OF "FREON" 113 (CCl₂F-CClF₂)

A. F. Benning and R. C. McHarness

THESE tables are the result of a research program which was undertaken to provide the refrigeration industry with tables of the thermodynamic properties of "Freon" 113 which would be characterized by completeness in both the saturated and superheat ranges, thermodynamic consistency, and a satisfactory degree of accuracy. Inasmuch as the literature contains very little information about "Freon" 113 it was necessary to determine experimentally all the physical properties that were needed for the calculation of the tables. The methods used were those generally accepted as giving results of sufficient accuracy. The experimental ranges covered were such as would permit the calculation of tables which were both complete and consistent.

The following physical properties were measured over the indicated ranges:

- (1) Vapor pressure between 1.5 and 475 lbs. per sq. in. abs.
- (2) Pressure-volume-temperature relationships of the superheated vapor over the pressure range of 5 to 310 lb. per sq. in. abs.
- (3) Density of the liquid between -20°F. and +410°F.
- (4) Specific heat of the vapor at constant pressure of one atmosphere (c_p) at 185°F. and 275°F.
- (5) Specific heat of the liquid at 10°, 35°, 75°, 110° and 145°F.
- (6) The ratio (c_p/c_v) of the vapor at 170°F. and 210°F.

The equations derived from the experimental measurements outlined above and which were used to calculate the tables of thermodynamic properties are given below.

t —temperature in °F.

T —temperature in °R. = °F. + 459.6

p —pressure in lb. per sq. in. abs.

v —volume of the vapor in ft.³ per lb.

d —density of the vapor in lb. per ft.³ = $1/v$.

d_l —density of the liquid in lb. per ft.³

c_p —specific heat of the vapor at constant pressure in Btu. per lb. per °F.

- (1) Vapor pressure

$$\log_{10} p = 33.0655 - \frac{4330.98}{T} - 9.2635 \log_{10} T + 0.0020539T.$$

- (2) Equation of State (Beattie-Bridgeman)

$$p = (0.0000500T - 0.0214)d^3 + (0.002618T - 4.035)d^2 + 0.05728Td$$

- (3) Liquid Density

$$d_l = 103.555 - 0.07126t - 0.0000636t^2$$

- (4) Specific heat of the Vapor at Constant Pressure.

$$c_p (1 \text{ atm.}) = 0.1455 + 0.000111t$$

The equations given above, which represent the experimentally determined properties of this material, were used to define a complete consistent thermodynamic network. Equations interrelating the quantities needed for the tables were obtained therefrom and used for the calculation of the tabular values.

All the saturated values of the pressure, volume, density, latent heat of vaporization and entropy of vaporization were calculated directly from the equations. The tabular values of the heat content of the saturated vapor and entropy of the liquid were obtained by interpolation between exact values calculated at 50°F. intervals. This interpolation was of such a nature that the method did not introduce any significant deviation from values obtained directly from the equations.

A large scale plot of the deviation of the superheated vapor from the ideal gas equation was prepared from values calculated from the experimentally determined equation of state, at 20°F. intervals of temperature and intervals of approximately 2% in the deviation. The tabular values of the superheat volume were then obtained by individual calculation of the ideal gas volume followed by correction from the deviation plot. This method did not introduce errors greater than 0.1%.

The heat content of the superheated vapor was calculated at 10°F. intervals of temperature along isometrics at the lowest and highest densities occurring in the saturated table and at 50°F. intervals along three intermediate isometrics. The equations used in these calculations were those which show the change in the heat content of the vapor at constant volume and at constant temperature. They were derived from equations (1) to (4) by the use of various well known thermodynamic relationships. The heat contents at tabular values of pressure and temperature were obtained from these data by suitable methods of interpolation.

The entropy of the superheated vapor was calculated at 50°F. intervals of temperature and at tabular values of pressure with the aid of the table of superheat volumes and the equations showing the change in the entropy of the vapor at constant volume and at constant temperature. Intermediate values were determined by an interpolation method which made use of the previously calculated values of the heat content of the superheated vapor. In all

cases the interpolation methods used were refined to such an extent that they introduced no appreciable errors into the results.

The tables are necessarily consistent because only the minimum number of equations necessary for their calculation were used and these equations were exactly interrelated. Arithmetical accuracy was checked by the independent calculation of one-fifth of the entire table. Less than one percent of these values showed any significant deviation from those in the complete tables and these were recalculated. All vertical differences in the final tables were checked, and any values that were out of line were recalculated. In addition, the differences between respective constant pressure tables in the superheat region were checked at two temperatures. As a result of these precautions it is felt that the tables are practically free from arithmetical errors.

The overall accuracy of the tables may be judged by calculating certain additional properties from the data at hand and comparing the results with those obtained from independent experimental measurements. Thus, the specific heat of the liquid can be determined from the heat contents of the liquid given in the table of saturated properties and compared with experimental values. The tables give values of 0.203, 0.214 and 0.233 B.T.U. per lb. per F. at 11°, 73° and 146°F. respectively. The corresponding quantities, as determined by direct calorimetric measurements, were 0.212, 0.220 and 0.223. The ratio of c_p to c_v at a pressure of one atmosphere was calculated as 1.077 at 171°F. and 1.073 at 212°F. The corresponding experimental values, as determined from the speed of sound in "Freon" 113 vapor, were 1.081 and 1.077. These quantities are in good agreement and constitute an excellent check on the accuracy of the tables and the data and equations from which they were derived.

In the low temperature portion of the table, namely below 10°F., the accuracy of the data is not as good as that of the remainder of the table. It is estimated that errors in this region may amount to several percent. Inaccuracies in this portion of the table do not affect the rest of the data because the methods of calculation were designed to eliminate such effects.

This work was made possible through the facilities of the Jackson Laboratory, E. I. du Pont de Nemours & Company.

NOTATION. The symbols used in this circular are taken from the American Standard Symbols for Heat and Thermodynamics, except in the case of tables of superheated properties for volume, heat content and entropy (V, H, S). Properly these are unit quantities and should be symbolized by lower case letters but the capitals are retained for legibility.

PHYSICAL PROPERTIES OF TRICHLOROTRIFLUOROETHANE "FREON" 113

Chemical Formula— $\text{CCl}_2\text{F}-\text{CClF}_2$
Molecular Weight—187.39
Boiling Point (760 mm—1 atm.)
17.6°F. (-4.6°C.)
Melting Point -31°F. (-35°C.)
Critical Temperature—417.4°F. (214.1°C.)
Critical Pressure—495 lbs./in.² abs.
Color—Clear and water white
Odor—Ethereal and similar to Carbon tetrachloride
Moisture—Not more than 0.0025% by weight
High Boiling Impurities—Not more than 0.05% by volume
Chlorides—None
Toxicity—Much less toxic than Group 4.
Classification of Underwriters' Laboratories Report MH 3072—page 14.
Flammability—Noncombustible and nonflammable. Underwriters' Laboratories Report MH3072—page 16.

	Temp. °F.	c_p	c_v	c_p/c_v
Specific Heat of Vapor (1 atm.)	160	0.1633	0.1516	1.077
	210	.1688	.1573	1.073
	260	0.1744	0.1630	1.070

	°F.	Vapor	Liquid (Saturation Pressure) Centipoises
Viscosity	-20	0.0090	1.566
	0	.0093	1.263
	20	.0095	1.043
	40	.0098	0.876
	60	.0101	.747
	80	.0103	.646
	100	.0106	.564
	120	.0108	.497
	140	.0111	.442
	160	.0113	.395
	180	.0116	.356
	200	.0118	.322
	220	.0120	.293
	240	0.0123	0.268

PROPERTIES OF SATURATED VAPOR

Temp. ° F t	Pressure		Volume		Density		Heat Content from -40°			Entropy from -40°		Temp. ° F t
	Abn. lb./in. ² p	Gage lb./in. ² p _g	Liquid ft. ³ /lb. v _l	Vapor ft. ³ /lb. v _g	Liquid lb./ft. ³ 1/v _l	Vapor lb./ft. ³ 1/v _g	Liquid Btu./lb. h _f	Latent Btu./lb. h _{fg}	Vapor Btu./lb. h _g	Liquid Btu./lb.°F. s _f	Vapor Btu./lb.°F. s _g	
-30	0.2987	29.31*	0.00947	82.26	105.64	0.01216	1.97	72.68	74.65	0.0047	0.1738	-30
-28	.3214	29.27*	.00948	76.81	105.50	.01302	2.36	72.57	74.93	.0056	.1737	-28
-26	.3458	29.22*	.00949	71.71	105.37	.01395	2.76	72.45	75.21	.0065	.1736	-26
-24	.3718	29.16*	.00950	66.99	105.23	.01493	3.16	72.33	75.49	.0074	.1735	-24
-22	.3995	29.11*	.00952	62.63	105.09	.01597	3.56	72.21	75.77	.0083	.1733	-22
-20	0.4288	29.05*	0.00953	58.61	104.96	0.01706	3.96	72.09	76.05	0.0092	0.1732	-20
-18	.4600	28.98*	.00954	54.88	104.82	.01822	4.36	71.98	76.34	.0101	.1731	-18
-16	.4931	28.92*	.00955	51.42	104.68	.01945	4.76	71.86	76.62	.0110	.1730	-16
-14	.5280	28.85*	.00957	48.23	104.54	.02074	5.16	71.74	76.90	.0119	.1729	-14
-12	.5652	28.77*	.00958	45.25	104.40	.02210	5.56	71.62	77.18	.0128	.1729	-12
-10	0.6046	28.69*	0.00959	42.48	104.26	0.02354	5.96	71.51	77.47	0.0137	0.1728	-10
-8	.6462	28.60*	.00960	39.92	104.12	.02505	6.36	71.39	77.75	.0146	.1727	-8
-6	.6902	28.51*	.00962	37.54	103.98	.02664	6.76	71.27	78.03	.0155	.1726	-6
-4	.7369	28.42*	.00963	35.31	103.84	.02832	7.17	71.15	78.32	.0164	.1726	-4
-2	.7860	28.32*	.00964	33.24	103.70	.03009	7.57	71.03	78.60	.0173	.1725	-2
0	0.8377	28.21*	0.00966	31.31	103.56	0.03194	7.98	70.92	78.89	0.0182	0.1725	0
2	.8924	28.10*	.00967	29.52	103.41	.03388	8.38	70.80	79.18	.0190	.1724	2
4	.9503	27.99*	.00968	27.84	103.27	.03592	8.78	70.68	79.46	.0199	.1724	4
5†	0.9802	27.92*	.00969	27.04	103.20	.03698	8.98	70.62	79.60	.0203	.1723	5†
6	1.011	27.86*	.00970	26.27	103.13	.03806	9.19	70.56	79.75	.0208	.1723	6
8	1.075	27.73*	.00971	24.81	102.98	.04031	9.59	70.44	80.03	.0216	.1723	8
10	1.142	27.60*	0.00972	23.45	102.84	0.04265	10.00	70.32	80.32	0.0225	0.1723	10
12	1.213	27.45*	.00974	22.17	102.69	.04511	10.41	70.20	80.61	.0234	.1722	12
14	1.288	27.30*	.00975	20.97	102.55	.04769	10.81	70.08	80.89	.0242	.1722	14
16	1.366	27.14*	.00977	19.84	102.40	.05040	11.22	69.96	81.18	.0251	.1722	16
18	1.448	26.97*	.00978	18.79	102.25	.05322	11.62	69.84	81.46	.0259	.1722	18
20	1.534	26.80*	0.00979	17.81	102.10	0.05616	12.03	69.72	81.75	0.0268	0.1722	20
22	1.624	26.61*	.00981	16.89	101.96	.05922	12.44	69.60	82.04	.0276	.1721	22
24	1.719	26.42*	.00982	16.02	101.81	.06243	12.85	69.48	82.33	.0285	.1721	24
26	1.818	26.22*	.00984	15.20	101.66	.06579	13.26	69.36	82.62	.0293	.1722	26
28	1.922	26.01*	.00985	14.43	101.51	.06929	13.67	69.24	82.91	.0302	.1722	28
30	2.031	25.79*	0.00987	13.71	101.36	0.07294	14.08	69.12	83.20	0.0310	0.1722	30
32	2.145	25.55*	.00988	13.03	101.21	.07675	14.49	69.00	83.49	.0318	.1722	32
34	2.264	25.31*	.00990	12.39	101.06	.08071	14.91	68.87	83.78	.0327	.1722	34
36	2.388	25.06*	.00991	11.79	100.91	.08483	15.32	68.75	84.07	.0335	.1722	36
38	2.519	24.79*	.00993	11.22	100.76	.08913	15.74	68.62	84.36	.0343	.1722	38
40	2.655	24.52*	0.00994	10.68	100.60	0.09361	16.16	68.50	84.65	0.0352	0.1723	40
42	2.797	24.23*	.00996	10.18	100.45	.09826	16.57	68.37	84.94	.0360	.1723	42
44	2.944	23.93*	.00997	9.703	100.30	.1031	16.99	68.25	85.24	.0368	.1723	44
46	3.098	23.61*	.00999	9.253	100.14	.1081	17.41	68.12	85.53	.0377	.1724	46
48	3.258	23.29*	.01000	8.830	99.99	.1133	17.82	68.00	85.82	.0385	.1724	48
50	3.427	22.94*	0.01002	8.426	99.83	0.1187	18.24	67.87	86.11	0.0393	0.1725	50
52	3.602	22.59*	.01003	8.044	99.68	.1243	18.66	67.74	86.40	.0401	.1726	52
54	3.784	22.22*	.01005	7.682	99.52	.1302	19.08	67.61	86.69	.0410	.1726	54
56	3.973	21.83*	.01006	7.342	99.37	.1362	19.50	67.48	86.98	.0418	.1727	56
58	4.170	21.43*	.01008	7.018	99.11	.1425	19.93	67.35	87.28	.0426	.1727	58
60	4.374	21.02*	0.01010	6.713	99.05	0.1490	20.35	67.22	87.57	0.0434	0.1728	60
62	4.586	20.59*	.01011	6.424	98.89	.1557	20.77	67.09	87.86	.0442	.1729	62
64	4.807	20.14*	.01013	6.149	98.73	.1626	21.19	66.96	88.15	.0450	.1729	64
66	5.036	19.67*	.01015	5.889	98.58	.1698	21.62	66.83	88.45	.0459	.1730	66
68	5.275	19.18*	.01016	5.640	98.42	.1773	22.05	66.69	88.74	.0467	.1731	68
70	5.523	18.68*	0.01018	5.404	98.26	0.1851	22.48	66.56	89.04	0.0475	0.1731	70
72	5.780	18.16*	.01019	5.180	98.10	.1931	22.90	66.43	89.33	.0483	.1732	72
74	6.042	17.62*	.01021	4.971	97.93	.2012	23.33	66.29	89.62	.0491	.1733	74
76	6.320	17.07*	.01023	4.769	97.77	.2097	23.76	66.16	89.92	.0499	.1734	76
78	6.607	16.47*	.01025	4.574	97.61	.2186	24.19	66.02	90.21	.0507	.1735	78
80	6.902	15.87*	0.01026	4.392	97.45	0.2277	24.63	65.88	90.51	0.0515	0.1736	80
82	7.208	15.25*	.01028	4.218	97.28	.2371	25.06	65.74	90.80	.0523	.1737	82
84	7.527	14.60*	.01030	4.051	97.12	.2468	25.49	65.60	91.09	.0531	.1738	84
86†	7.856	13.93*	.01031	3.893	96.96	.2569	25.93	65.46	91.39	.0539	.1739	86†
88	8.194	13.24*	.01033	3.742	96.79	.2672	26.36	65.32	91.68	.0547	.1740	88

* Inches of mercury below one atmosphere.
† Standard ion temperatures.

PROPERTIES OF SATURATED VAPOR

Temp. ° F. t	Pressure		Volume		Density		Heat Content from -10°			Entropy from -10°		Temp. ° F. t
	Abs. lb./in. ² p	Gage lb./in. ² p _g	Liquid ft. ³ /lb. v _l	Vapor ft. ³ /lb. v _g	Liquid lb./ft. ³ 1/v _l	Vapor lb./ft. ³ 1/v _g	Liquid Btu./lb. h _f	Latent Btu./lb. h	Vapor Btu./lb. h _g	Liquid Btu./lb.°F. s _f	Vapor Btu./lb.°F. s _g	
90	8.545	12.53*	0.01035	3.600	96.63	0.2778	26.80	65.18	91.98	0.0555	0.1741	90
92	8.908	11.79*	.01037	3.463	96.46	.2888	27.24	65.04	92.28	.0563	.1742	92
94	9.281	11.03*	.01039	3.333	96.30	.3001	27.67	64.90	92.57	.0571	.1743	94
96	9.668	10.24*	.01040	3.208	96.13	.3117	28.11	64.75	92.86	.0578	.1744	96
98	10.07	9.42*	.01042	3.089	95.96	.3237	28.55	64.60	93.15	.0586	.1745	98
100	10.48	8.59*	0.01044	2.976	95.79	0.3360	28.99	64.46	93.45	0.0594	0.1746	100
102	10.91	7.71*	.01046	2.867	95.63	.3488	29.44	64.31	93.75	.0602	.1747	102
104	11.35	6.82*	.01048	2.762	95.46	.3620	29.89	64.16	94.05	.0610	.1748	104
106	11.81	5.88*	.01050	2.662	95.29	.3756	30.33	64.01	94.34	.0618	.1750	106
108	12.28	4.93*	.01051	2.567	95.12	.3896	30.78	63.86	94.64	.0626	.1751	108
110	12.76	3.95*	0.01053	2.477	94.95	0.4038	31.22	63.71	94.93	0.0634	0.1752	110
112	13.25	2.95*	.01055	2.391	94.78	.4182	31.67	63.56	95.23	.0641	.1753	112
114	13.76	1.91*	.01057	2.308	94.61	.4333	32.12	63.40	95.52	.0649	.1755	114
116	14.29	0.83*	.01059	2.228	94.43	.4489	32.57	63.25	95.82	.0657	.1756	116
118	14.84	0.14	.01061	2.151	94.26	.4649	33.03	63.09	96.12	.0665	.1757	118
120	15.40	0.70	0.01063	2.078	94.09	0.4813	33.48	62.93	96.41	0.0673	0.1758	120
122	15.97	1.27	.01065	2.008	93.92	.4981	33.93	62.78	96.71	.0680	.1760	122
124	16.56	1.86	.01067	1.941	93.74	.5153	34.38	62.62	97.00	.0688	.1761	124
126	17.17	2.47	.01069	1.876	93.57	.5330	34.83	62.46	97.29	.0696	.1763	126
128	17.80	3.10	.01071	1.814	93.39	.5514	35.29	62.30	97.59	.0704	.1764	128
130	18.45	3.74	0.01073	1.754	93.22	0.5702	35.75	62.14	97.89	0.0712	0.1765	130
132	19.11	4.41	.01075	1.697	93.04	.5894	36.21	61.97	98.18	.0719	.1767	132
134	19.79	5.09	.01077	1.642	92.86	.6091	36.67	61.80	98.47	.0727	.1768	134
136	20.48	5.78	.01079	1.590	92.69	.6290	37.13	61.64	98.77	.0735	.1770	136
138	21.19	6.49	.01081	1.540	92.51	.6494	37.59	61.48	99.06	.0742	.1771	138
140	21.93	7.23	0.01083	1.491	92.33	0.6707	38.05	61.31	99.36	0.0750	0.1773	140
142	22.69	7.99	.01085	1.444	92.15	.6926	38.52	61.13	99.65	.0758	.1774	142
144	23.47	8.77	.01087	1.399	91.98	.7150	38.98	60.96	99.94	.0765	.1775	144
146	24.27	9.57	.01089	1.355	91.80	.7379	39.45	60.79	100.24	.0773	.1777	146
148	25.09	10.39	.01092	1.313	91.62	.7615	39.92	60.61	100.53	.0781	.1778	148
150	25.93	11.23	0.01094	1.273	91.44	0.7856	40.38	60.44	100.82	0.0789	0.1780	150
152	26.79	12.09	.01096	1.234	91.25	.8102	40.85	60.27	101.11	.0796	.1782	152
154	27.67	12.97	.01098	1.197	91.07	.8353	41.32	60.09	101.41	.0804	.1783	154
156	28.56	13.86	.01100	1.162	90.89	.8608	41.79	59.91	101.70	.0812	.1785	156
158	29.48	14.78	.01102	1.128	90.71	.8869	42.26	59.73	101.99	.0819	.1786	158
160	30.44	15.74	0.01105	1.094	90.53	0.9141	42.74	59.55	102.29	0.0827	0.1788	160
170	35.53	20.83	.01116	0.9442	89.60	1.059	45.12	58.62	103.74	.0865	.1796	170
180	41.22	26.52	.01128	.8193	88.67	1.221	47.53	57.66	105.19	.0903	.1804	180
190	47.60	32.90	.01140	.7134	87.72	1.402	49.97	56.66	106.63	.0940	.1813	190
200	54.66	39.96	.01153	.6241	86.76	1.602	52.45	55.62	108.07	.0978	.1821	200
210	62.50	47.80	.01166	.5477	85.79	1.826	54.96	54.54	109.50	.1015	.1830	210
220	71.07	56.37	0.01179	0.4827	84.80	2.072	57.49	53.43	110.92	0.1052	0.1839	220

PROPERTIES OF SUPERHEATED VAPOUR—Continued

Temp. ° F	Abs. Pressure 0.3 lb./in. ² Gauge Pressure 29.31 in. Vac. (Sat'n. Temp. -29.9° F.)			Abs. Pressure 0.4 lb./in. ² Gauge Pressure 29.11 in. Vac. (Sat'n. Temp. -22.0° F.)			Abs. Pressure 0.5 lb./in. ² Gauge Pressure 28.90 in. Vac. (Sat'n. Temp. -15.0° F.)			Abs. Pressure 0.6 lb./in. ² Gauge Pressure 28.70 in. Vac. (Sat'n. Temp. -10.2° F.)		
	t	V	H	S	V	H	S	V	H	S	V	H
(At sat'n.)	(81.95)	(74.66)	(0.1738)	(62.55)	(75.77)	(0.1733)	(50.79)	(76.68)	(0.1730)	(42.81)	(77.44)	(0.1728)
-20	83.83	76.06	0.1770	62.32	76.05	0.1740
-10	85.74	77.48	.1802	64.25	77.47	.1772	51.43	77.47	0.1748	42.83	77.47	0.1729
0	87.65	78.91	0.1834	65.68	78.90	0.1803	52.58	78.90	0.1779	43.79	78.90	0.1760
10	89.55	80.35	.1865	67.11	80.34	.1834	53.72	80.34	.1810	44.74	80.34	.1791
20	91.46	81.80	.1895	68.63	81.80	.1865	54.87	81.79	.1841	45.70	81.79	.1822
30	93.37	83.26	.1925	70.06	83.26	.1895	56.01	83.26	.1871	46.65	83.25	.1852
40	95.27	84.74	.1955	71.49	84.74	.1925	57.16	84.73	.1901	47.61	84.73	.1882
50	97.18	86.23	0.1985	72.92	86.22	0.1954	58.31	86.22	0.1931	48.56	86.22	0.1911
60	99.09	87.73	.2014	74.35	87.72	.1983	59.47	87.72	.1960	49.52	87.72	.1940
70	101.0	89.24	.2043	75.79	89.23	.2012	60.63	89.23	.1989	50.47	89.23	.1969
80	102.9	90.76	.2071	77.22	90.76	.2041	61.78	90.75	.2017	51.43	90.75	.1998
90	104.8	92.29	.2099	78.65	92.29	.2069	62.93	92.28	.2045	52.38	92.28	.2026
100	106.7	93.83	0.2127	80.08	93.83	0.2097	64.07	93.83	0.2073	53.34	93.82	0.2054
110	108.6	95.40	.2155	81.51	95.39	.2124	65.21	95.39	.2101	54.31	95.39	.2081
120	110.5	96.97	.2182	82.94	96.96	.2152	66.36	96.96	.2128	55.27	96.96	.2109
130	112.4	98.55	.2209	84.37	98.54	.2179	67.51	98.54	.2155	56.22	98.54	.2136
140	114.3	100.14	.2236	85.80	100.13	.2206	68.65	100.13	.2182	57.18	100.13	.2162
150	116.3	101.74	0.2262	87.23	101.74	0.2232	69.80	101.73	0.2208	58.13	101.73	0.2189
160	118.2	103.36	.2289	88.66	103.35	.2258	70.94	103.35	.2234	59.09	103.34	.2215
170	120.1	104.98	.2315	90.10	104.98	.2284	72.09	104.98	.2260	60.04	104.97	.2241
180	122.0	106.62	.2342	91.53	106.62	.2310	73.23	106.61	.2286	60.99	106.61	.2267
190	124.0	108.27	.2366	92.96	108.27	.2336	74.38	108.26	.2312	61.95	108.26	.2293
200	125.9	109.93	0.2392	94.39	109.93	0.2361	75.52	109.92	0.2337	62.90	109.92	0.2318
210	127.8	111.61	.2417	95.82	111.61	.2386	76.67	111.60	.2363	63.85	111.60	.2343
220	129.7	113.30	.2442	97.25	113.30	.2411	77.81	113.29	.2388	64.81	113.29	.2368
230	131.6	115.00	.2467	98.68	114.99	.2436	78.96	114.99	.2412	65.76	114.99	.2393
240	133.6	116.71	.2491	100.1	116.70	.2461	80.10	116.70	.2437	66.71	116.70	.2418
250	135.5	118.42	0.2516	101.5	118.42	0.2485	81.25	118.42	0.2461	67.67	118.41	0.2442
260	137.4	120.15	.2540	103.0	120.15	.2509	82.39	120.15	.2486	68.62	120.14	.2466
270	139.3	121.89	.2564	104.4	121.88	.2533	83.54	121.88	.2510	69.57	121.87	.2490
280	141.2	123.64	0.2588	105.9	123.63	0.2557	84.68	123.63	.2533	70.53	123.62	.2514
290	85.83	125.40	0.2557	71.48	125.39	0.2538
Temp. ° F.	Abs. Pressure 0.7 lb./in. ² Gauge Pressure 28.50 in. Vac. (Sat'n. Temp. -5.5° F.)			Abs. Pressure 0.8 lb./in. ² Gauge Pressure 28.29 in. Vac. (Sat'n. Temp. -1.5° F.)			Abs. Pressure 0.9 lb./in. ² Gauge Pressure 28.09 in. Vac. (Sat'n. Temp. +2.3° F.)			Abs. Pressure 1.0 lb./in. ² Gauge Pressure 27.88 in. Vac. (Sat'n. Temp. 5.6° F.)		
(At sat'n.)	(37.05)	(78.10)	(0.1726)	(32.71)	(78.68)	(0.1725)	(29.30)	(79.22)	(0.1724)	(26.54)	(79.69)	(0.1723)
0	37.49	78.90	0.1743	32.81	78.89	0.1729
10	38.32	80.34	.1774	33.53	80.33	.1760	29.79	80.33	0.1748	26.79	80.32	0.1737
20	39.15	81.79	.1805	34.25	81.78	.1791	30.43	81.78	.1779	27.38	81.78	.1768
30	39.98	83.25	.1835	34.97	83.25	.1821	31.07	83.24	.1809	27.96	83.24	.1798
40	40.80	84.72	.1865	35.69	84.72	.1851	31.71	84.72	.1839	28.53	84.71	.1828
50	41.62	86.21	0.1895	36.41	86.21	0.1881	32.35	86.20	0.1868	29.10	86.20	0.1857
60	42.43	87.71	.1924	37.13	87.71	.1910	32.99	87.70	.1897	29.67	87.70	.1886
70	43.25	89.22	.1953	37.85	89.22	.1939	33.63	89.21	.1926	30.25	89.21	.1915
80	44.07	90.74	.1981	38.57	90.74	.1967	34.27	90.74	.1955	30.82	90.73	.1943
90	44.89	92.28	.2009	39.29	92.27	.1995	34.91	92.27	.1983	31.39	92.27	.1972
100	45.71	93.82	0.2037	40.01	93.82	0.2023	35.55	93.81	0.2011	31.97	93.81	0.2000
110	46.53	95.38	.2065	40.72	95.38	.2051	36.19	95.37	.2038	32.56	95.37	.2027
120	47.35	96.95	.2092	41.44	96.95	.2078	36.83	96.94	.2066	33.14	96.94	.2054
130	48.18	98.53	.2119	42.16	98.53	.2105	37.47	98.52	.2093	33.71	98.52	.2081
140	49.00	100.12	.2146	42.88	100.12	.2132	38.11	100.12	.2119	34.28	100.11	.2108
150	49.83	101.73	0.2172	43.60	101.72	0.2158	38.75	101.72	0.2146	34.85	101.72	0.2135
160	50.65	103.34	.2199	44.32	103.34	.2185	39.39	103.33	.2172	35.42	103.33	.2161
170	51.47	104.97	.2225	45.04	104.96	.2211	40.03	104.96	.2198	35.99	104.96	.2187
180	52.29	106.61	.2251	45.75	106.60	.2236	40.67	106.60	.2224	36.57	106.60	.2213
190	53.10	108.26	.2276	46.47	108.25	.2262	41.31	108.25	.2249	37.15	108.25	.2238
200	53.92	109.92	0.2302	47.18	109.91	0.2288	41.94	109.91	0.2275	37.73	109.91	0.2264
210	54.74	111.60	.2327	47.90	111.59	.2313	42.57	111.59	.2300	38.30	111.59	.2289
220	55.56	113.29	.2352	48.61	113.28	.2338	43.21	113.28	.2325	38.88	113.28	.2314
230	56.37	114.98	.2377	49.33	114.98	.2363	43.84	114.98	.2350	39.46	114.97	.2339
240	57.19	116.69	.2401	50.04	116.69	.2387	44.48	116.69	.2375	40.03	116.68	.2363
250	58.01	118.41	0.2426	50.76	118.41	0.2412	45.12	118.40	0.2399	40.60	118.40	0.2388
260	58.83	120.14	.2450	51.47	120.13	.2436	45.75	120.13	.2423	41.18	120.13	.2412
270	59.64	121.87	.2474	52.19	121.86	.2460	46.39	121.86	.2447	41.75	121.86	.2436
280	60.46	123.62	.2498	52.90	123.61	.2484	47.02	123.61	.2471	42.32	123.62	.2460
290	61.28	125.39	.2522	53.62	125.38	.2507	47.66	125.38	.2495	42.89	125.38	.2484
300	62.10	127.18	0.2545	54.34	127.17	0.2531	48.30	127.17	0.2518	43.46	127.16	0.2507
310	48.93	128.97	0.2542	44.04	128.96	0.2531

PROPERTIES OF SUPERHEATED VAPOR—Continued

Temp. ° F.	Abs. Pressure 1.1 lb./in. ² Gauge Pressure 27.68 in. Vac. (Sat'n. Temp. 8.7° F.)			Abs. Pressure 1.2 lb./in. ² Gauge Pressure 27.48 in. Vac. (Sat'n. Temp. 11.6° F.)			Abs. Pressure 1.3 lb./in. ² Gauge Pressure 27.27 in. Vac. (Sat'n. Temp. 14.3° F.)			Abs. Pressure 1.4 lb./in. ² Gauge Pressure 27.07 in. Vac. (Sat'n. Temp. 16.9° F.)		
	t	v	h	s	v	h	s	v	h	s	v	h
(At sat'n.)	(24.29)	(80.13)	(0.1723)	(22.40)	(80.55)	(0.1722)	(20.75)	(80.93)	(0.1722)	(19.40)	(81.30)	(0.1722)
10	24.35	80.32	0.1726
20	24.87	81.77	.1757	22.80	81.77	0.1748	21.03	81.76	0.1740	19.52	81.76	0.1731
30	25.39	83.24	.1787	23.28	83.23	.1778	21.47	83.23	.1770	19.93	83.23	.1762
40	25.91	84.71	.1817	23.75	84.71	.1808	21.91	84.70	.1800	20.35	84.70	.1792
50	26.43	86.20	0.1847	24.23	86.19	0.1837	22.36	86.19	0.1829	20.76	86.19	0.1821
60	26.96	87.70	.1876	24.71	87.69	.1866	22.80	87.69	.1858	21.17	87.69	.1850
70	27.49	89.21	.1905	25.19	89.20	.1895	23.24	89.20	.1887	21.58	89.20	.1879
80	28.01	90.73	.1933	25.67	90.72	.1924	23.68	90.72	.1915	21.99	90.72	.1907
90	28.53	92.26	.1961	26.15	92.26	.1952	24.13	92.26	.1944	22.40	92.25	.1935
100	29.05	93.81	0.1989	26.63	93.80	0.1980	24.58	93.80	0.1971	22.81	93.80	0.1963
110	29.57	95.37	.2017	27.11	95.36	.2007	25.02	95.36	.1999	23.22	95.36	.1991
120	30.09	96.94	.2044	27.59	96.93	.2035	25.46	96.93	.2026	23.63	96.93	.2018
130	30.62	98.52	.2071	28.07	98.51	.2062	25.90	98.51	.2053	24.04	98.51	.2045
140	31.15	100.11	.2098	28.55	100.10	.2089	26.34	100.10	.2080	24.45	100.10	.2072
150	31.68	101.71	0.2124	29.03	101.71	0.2115	26.78	101.70	0.2106	24.86	101.70	0.2099
160	32.20	103.33	.2151	29.51	103.32	.2141	27.23	103.32	.2133	25.27	103.32	.2125
170	32.72	104.95	.2177	29.99	104.95	.2167	27.68	104.95	.2159	25.68	104.94	.2151
180	33.24	106.59	.2202	30.47	106.59	.2193	28.12	106.59	.2185	26.10	106.58	.2177
190	33.76	108.24	.2228	30.95	108.24	.2219	28.56	108.24	.2211	26.52	108.23	.2202
200	34.28	109.90	0.2253	31.43	109.90	0.2244	29.00	109.90	0.2236	26.93	109.89	0.2228
210	34.80	111.58	.2279	31.91	111.58	.2270	29.44	111.58	.2261	27.34	111.57	.2253
220	35.32	113.27	.2304	32.39	113.27	.2295	29.88	113.27	.2286	27.75	113.26	.2278
230	35.85	114.97	.2329	32.87	114.97	.2319	30.32	114.96	.2311	28.16	114.96	.2303
240	36.37	116.68	.2353	33.35	116.68	.2344	30.76	116.67	.2335	28.57	116.67	.2328
250	36.90	118.40	0.2378	33.83	118.39	0.2368	31.20	118.39	0.2360	28.98	118.39	0.2352
260	37.43	120.13	.2402	34.31	120.12	.2393	31.64	120.12	.2384	29.39	120.12	.2374
270	37.95	121.86	.2426	34.79	121.86	.2417	32.08	121.86	.2408	29.80	121.85	.2400
280	38.47	123.61	.2450	35.26	123.61	.2441	32.53	123.61	.2432	30.21	123.60	.2424
290	38.99	125.38	.2474	35.74	125.38	.2464	32.98	125.37	.2456	30.62	125.37	.2448
300	39.51	127.16	0.2497	36.22	127.16	0.2488	33.43	127.16	0.2479	31.03	127.16	0.2471
310	40.03	128.96	0.2521	36.69	128.96	.2511	33.88	128.96	.2503	31.44	128.95	.2495
320	37.17	130.76	0.2535	34.32	130.76	0.2526	31.85	130.75	0.2518
Temp. ° F.	Abs. Pressure 1.6 lb./in. ² Gauge Pressure 28.66 in. Vac. (Sat'n. Temp. 21.3° F.)			Abs. Pressure 1.8 lb./in. ² Gauge Pressure 28.26 in. Vac. (Sat'n. Temp. 25.6° F.)			Abs. Pressure 2.0 lb./in. ² Gauge Pressure 27.85 in. Vac. (Sat'n. Temp. 29.4° F.)			Abs. Pressure 2.2 lb./in. ² Gauge Pressure 27.44 in. Vac. (Sat'n. Temp. 32.9° F.)		
(At sat'n.)	(17.13)	(81.97)	(0.1721)	(15.35)	(82.57)	(0.1722)	(13.91)	(83.12)	(0.1722)	(12.74)	(83.82)	(0.1722)
30	17.43	83.22	0.1747	15.49	83.21	0.1735	13.92	83.20	0.1724
40	17.79	84.69	.1777	15.81	84.68	.1765	14.21	84.68	.1753	12.92	84.67	0.1743
50	18.15	86.18	0.1807	16.13	86.17	0.1794	14.50	86.16	0.1783	13.18	86.16	0.1773
60	18.51	87.68	.1836	16.45	87.67	.1823	14.79	87.66	.1812	13.44	87.66	.1802
70	18.87	89.19	.1865	16.77	89.18	.1852	15.08	89.17	.1841	13.70	89.17	.1831
80	19.23	90.71	.1893	17.09	90.70	.1881	15.37	90.69	.1869	13.96	90.69	.1859
90	19.59	92.24	.1921	17.41	92.24	.1909	15.66	92.23	.1898	14.22	92.22	.1887
100	19.95	93.79	0.1949	17.73	93.78	0.1937	15.95	93.77	0.1926	14.48	93.77	0.1915
110	20.31	95.35	.1977	18.05	95.34	.1964	16.24	95.33	.1953	14.75	95.33	.1943
120	20.67	96.92	.2004	18.37	96.91	.1992	16.53	96.90	.1980	15.02	96.90	.1970
130	21.03	98.50	.2031	18.69	98.49	.2019	16.82	98.49	.2007	15.28	98.49	.1997
140	21.39	100.09	.2058	19.01	100.08	.2045	17.11	100.09	.2034	15.54	100.08	.2024
150	21.75	101.69	0.2084	19.33	101.69	0.2072	17.39	101.69	0.2061	15.81	101.68	0.2051
160	22.11	103.31	.2111	19.65	103.31	.2098	17.68	103.31	.2087	16.07	103.30	.2077
170	22.47	104.94	.2137	19.97	104.93	.2124	17.96	104.93	.2113	16.33	104.93	.2103
180	22.83	106.58	.2163	20.29	106.57	.2150	18.25	106.57	.2139	16.59	106.56	.2129
190	23.19	108.22	.2188	20.61	108.22	.2176	18.54	108.22	.2164	16.85	108.21	.2154
200	23.55	109.89	0.2214	20.93	109.88	0.2201	18.83	109.88	0.2190	17.11	109.88	0.2180
210	23.91	111.57	.2239	21.25	111.56	.2226	19.12	111.56	.2215	17.38	111.55	.2205
220	24.27	113.26	.2264	21.57	113.25	.2251	19.40	113.24	.2240	17.64	113.24	.2230
230	24.63	114.95	.2289	21.89	114.95	.2276	19.69	114.94	.2265	17.90	114.93	.2255
240	24.99	116.66	.2313	22.21	116.66	.2301	19.97	116.65	.2290	18.16	116.64	.2279
250	25.35	118.38	0.2338	22.53	118.38	0.2325	20.26	118.37	0.2314	18.42	118.36	0.2304
260	25.71	120.11	.2362	22.85	120.11	.2349	20.55	120.10	.2338	18.68	120.09	.2328
270	26.07	121.85	.2386	23.17	121.84	.2373	20.84	121.84	.2362	18.94	121.83	.2352
280	26.43	123.60	.2410	23.49	123.59	.2397	21.13	123.59	.2386	19.20	123.58	.2376
290	26.78	125.37	.2434	23.81	125.36	.2421	21.42	125.36	.2409	19.47	125.35	.2400
300	27.14	127.16	0.2457	24.12	127.15	0.2445	21.71	127.15	0.2433	19.74	127.14	0.2423
310	27.50	128.95	.2481	24.44	128.94	.2468	22.00	128.94	.2457	20.00	128.93	.2447
320	27.86	130.75	.2504	24.76	130.74	.2491	22.28	130.74	.2480	20.26	130.73	.2470
330	28.23	132.56	0.2527	25.08	132.56	0.2514	22.57	132.55	0.2503	20.52	132.55	.2493
340	20.78	134.37	0.2516

PROPERTIES OF SUPERHEATED VAPOR—Continued

Temp. ° F	Abs. Pressure 2.4 lb./in. ² Gauge Pressure 25.04 in. Vac. (Sat'n. Temp. 36.2° F.)			Abs. Pressure 2.6 lb./in. ² Gauge Pressure 24.63 in. Vac. (Sat'n. Temp. 39.2° F.)			Abs. Pressure 2.8 lb./in. ² Gauge Pressure 24.22 in. Vac. (Sat'n. Temp. 42.0° F.)			Abs. Pressure 3.0 lb./in. ² Gauge Pressure 23.81 in. Vac. (Sat'n. Temp. 44.7° F.)		
	t	v	h	s	v	h	s	v	h	s	v	h
(At sat'n.)	(11.74)	(64.10)	(0.1722)	(10.89)	(84.53)	(0.1723)	(10.17)	(84.94)	(0.1723)	(9.537)	(85.34)	(0.1723)
40	11.84	84.66	0.1734	10.91	84.65	0.1725
50	12.08	86.15	0.1763	11.13	86.14	0.1755	10.33	86.13	0.1747	9.637	86.12	0.1739
60	12.32	87.65	.1792	11.35	87.64	.1784	10.54	87.63	.1776	9.831	87.62	.1769
70	12.56	89.16	.1821	11.58	89.15	.1813	10.75	89.14	.1805	10.02	89.13	.1797
80	12.80	90.68	.1850	11.80	90.67	.1841	10.95	90.66	.1833	10.22	90.66	.1826
90	13.04	92.21	.1878	12.02	92.21	.1869	11.16	92.20	.1861	10.41	92.19	.1854
100	13.28	93.76	0.1906	12.24	93.75	0.1897	11.37	93.74	0.1889	10.60	93.74	0.1882
110	13.52	95.32	.1934	12.47	95.31	.1925	11.58	95.30	.1917	10.80	95.30	.1910
120	13.76	96.89	.1961	12.69	96.88	.1952	11.79	96.87	.1944	10.99	96.87	.1937
130	14.00	98.48	.1988	12.91	98.47	.1979	11.99	98.46	.1971	11.18	98.46	.1964
140	14.24	100.07	.2015	13.13	100.06	.2006	12.20	100.06	.1998	11.38	100.05	.1991
150	14.48	101.68	0.2041	13.36	101.67	0.2033	12.40	101.66	0.2025	11.57	101.65	0.2017
160	14.72	103.29	.2068	13.58	103.28	.2059	12.61	103.28	.2051	11.76	103.27	.2044
170	14.96	104.92	.2094	13.80	104.91	.2085	12.82	104.90	.2077	11.95	104.90	.2070
180	15.20	106.56	.2099	14.02	106.55	.2111	13.02	106.54	.2103	12.15	106.54	.2095
190	15.44	108.21	.2145	14.25	108.20	.2137	13.23	108.19	.2129	12.34	108.19	.2121
200	15.68	109.87	0.2171	14.47	109.86	0.2162	13.44	109.86	0.2154	12.53	109.85	0.2147
210	15.93	111.54	.2196	14.69	111.54	.2187	13.65	111.54	.2179	12.72	111.53	.2172
220	16.17	113.23	.2221	14.91	113.22	.2212	13.85	113.23	.2204	12.92	113.22	.2197
230	16.41	114.93	.2246	15.13	114.92	.2237	14.05	114.92	.2229	13.11	114.92	.2222
240	16.65	116.64	.2270	15.35	116.63	.2262	14.26	116.63	.2254	13.30	116.63	.2246
250	16.89	118.35	0.2295	15.58	118.35	0.2286	14.46	118.35	0.2278	13.49	118.35	0.2271
260	17.13	120.08	.2319	15.80	120.08	.2310	14.67	120.08	.2302	13.68	120.08	.2295
270	17.37	121.82	.2343	16.02	121.82	.2334	14.88	121.82	.2326	13.87	121.82	.2319
280	17.61	123.58	.2367	16.24	123.57	.2358	15.09	123.57	.2350	14.06	123.57	.2343
290	17.85	125.35	.2391	16.46	125.34	.2382	15.29	125.34	.2374	14.26	125.33	.2367
300	18.09	127.14	0.2414	16.68	127.13	0.2406	15.50	127.13	0.2398	14.46	127.11	0.2390
310	18.33	128.93	.2437	16.90	128.92	.2429	15.70	128.92	.2421	14.65	128.91	.2414
320	18.57	130.73	.2461	17.12	130.72	.2452	15.90	130.73	.2444	14.84	130.71	.2437
330	18.81	132.54	.2484	17.34	132.54	.2475	16.11	132.54	.2467	15.03	132.52	.2460
340	19.05	134.36	0.2507	17.56	134.36	0.2498	16.31	134.36	.2490	15.22	134.35	.2483
350	16.52	136.20	0.2513	15.41	136.19	0.2505
Temp. ° F.	Abs. Pressure 3.2 lb./in. ² Gauge Pressure 23.41 in. Vac. (Sat'n. Temp. 47.3° F.)			Abs. Pressure 3.4 lb./in. ² Gauge Pressure 23.00 in. Vac. (Sat'n. Temp. 49.7° F.)			Abs. Pressure 3.6 lb./in. ² Gauge Pressure 22.59 in. Vac. (Sat'n. Temp. 52.0° F.)			Abs. Pressure 3.8 lb./in. ² Gauge Pressure 22.19 in. Vac. (Sat'n. Temp. 54.2° F.)		
(At sat'n.)	(5.983)	(85.71)	(0.1724)	(8.489)	(86.06)	(0.1725)	(8.047)	(86.40)	(0.1725)	(7.633)	(86.72)	(0.1726)
50	9.030	86.12	0.1733	8.493	86.11	0.1726
60	9.209	87.62	.1762	8.665	87.61	.1755	8.177	87.60	0.1749	7.742	87.59	0.1743
70	9.391	89.13	.1791	8.837	89.12	.1784	8.338	89.11	.1778	7.895	89.10	.1772
80	9.573	90.65	.1819	9.009	90.64	.1813	8.499	90.63	.1806	8.048	90.62	.1800
90	9.755	92.18	.1847	9.181	92.18	.1841	8.659	92.17	.1834	8.201	92.16	.1829
100	9.938	93.73	0.1875	9.353	93.72	0.1869	8.819	93.71	0.1862	8.354	93.71	0.1857
110	10.12	95.29	.1903	9.525	95.28	.1896	8.980	95.27	.1890	8.506	95.27	.1884
120	10.30	96.86	.1930	9.697	96.85	.1924	9.141	96.84	.1917	8.659	96.84	.1911
130	10.48	98.45	.1957	9.869	98.44	.1951	9.305	98.43	.1944	8.812	98.43	.1938
140	10.66	100.04	.1984	10.03	100.03	.1977	9.466	100.03	.1971	8.965	100.02	.1965
150	10.84	101.65	0.2010	10.20	101.64	0.2004	9.627	101.63	0.1998	9.118	101.62	0.1992
160	11.02	103.26	.2037	10.37	103.26	.2030	9.788	103.25	.2024	9.271	103.24	.2018
170	11.20	104.89	.2063	10.54	104.89	.2056	9.948	104.88	.2050	9.423	104.87	.2044
180	11.38	106.54	.2089	10.71	106.53	.2082	10.11	106.53	.2076	9.576	106.52	.2070
190	11.56	108.19	.2114	10.88	108.18	.2108	10.27	108.18	.2102	9.729	108.17	.2096
200	11.74	109.85	0.2140	11.05	109.85	0.2133	10.43	109.84	0.2127	9.882	109.83	0.2121
210	11.92	111.53	.2165	11.22	111.52	.2159	10.59	111.51	.2153	10.03	111.51	.2147
220	12.10	113.21	.2190	11.39	113.21	.2184	10.75	113.20	.2178	10.19	113.19	.2172
230	12.28	114.91	.2215	11.56	114.90	.2208	10.91	114.90	.2202	10.34	114.89	.2196
240	12.47	116.62	.2240	11.73	116.61	.2233	11.07	116.61	.2227	10.49	116.60	.2221
250	12.65	118.34	0.2264	11.90	118.33	0.2257	11.23	118.32	0.2252	10.64	118.32	0.2245
260	12.83	120.06	.2288	12.07	120.05	.2282	11.40	120.05	.2276	10.79	120.04	.2270
270	13.01	121.80	.2312	12.24	121.79	.2306	11.56	121.79	.2300	10.95	121.78	.2294
280	13.19	123.55	.2336	12.41	123.55	.2330	11.72	123.54	.2324	11.10	123.53	.2318
290	13.37	125.32	.2360	12.58	125.32	.2353	11.88	125.31	.2347	11.25	125.30	.2341
300	13.56	127.11	0.2383	12.75	127.11	0.2377	12.04	127.10	0.2371	11.40	127.09	0.2365
310	13.74	128.90	.2407	12.92	128.90	.2409	12.20	128.89	.2394	11.55	128.89	.2388
320	13.92	130.70	.2430	13.09	130.70	.2425	12.36	130.69	.2417	11.70	130.69	.2412
330	14.09	132.52	.2453	13.26	132.51	.2446	12.52	132.51	.2441	11.85	132.50	.2435
340	14.27	134.34	.2476	13.43	134.34	.2469	12.68	134.33	.2464	12.00	134.33	.2458
350	14.45	136.18	0.2499	13.60	136.18	0.2492	12.84	136.17	0.2486	12.15	136.17	0.2481
360	13.00	138.02	0.2509	12.31	138.01	0.2503

PROPERTIES OF SUPERHEATED VAPOR—Continued

Temp. ° F.	Abs. Pressure 4.0 lb./in. ² Gauge Pressure 21.73 in. Vac. (Sat'n. Temp. 58.3° F.)			Abs. Pressure 4.5 lb./in. ² Gauge Pressure 20.74 in. Vac. (Sat'n. Temp. 61.2° F.)			Abs. Pressure 5.0 lb./in. ² Gauge Pressure 19.74 in. Vac. (Sat'n. Temp. 63.7° F.)			Abs. Pressure 5.5 lb./in. ² Gauge Pressure 18.73 in. Vac. (Sat'n. Temp. 69.8° F.)		
	V	H	S	V	H	S	V	H	S	V	H	S
(At sat'n.)	(7.297)	(87.03)	(0.1727)	(6.542)	(87.74)	(0.1728)	(5.930)	(88.41)	(0.1730)	(5.428)	(89.01)	(0.1731)
60	7.351	87.58	0.1738	6.657	89.08	0.1754	5.979	89.06	0.1742	5.428	89.04	0.1732
70	7.497	89.10	.1767	6.786	90.60	.1782	6.096	90.58	.1771	5.533	90.56	.1761
80	7.642	90.62	.1795	6.915	92.13	.1810	6.213	92.12	.1799	5.638	92.10	.1789
90	7.787	92.15	.1823	7.044	93.68	.1838	6.329	93.67	.1827	5.743	93.64	.1817
100	7.932	93.70	0.1851	7.173	95.24	.1866	6.445	95.22	.1855	5.849	95.20	.1844
110	8.077	95.26	.1879	7.302	96.81	.1893	6.562	96.79	.1882	5.955	96.77	.1872
120	8.222	96.83	.1906	7.431	98.40	.1920	6.678	98.38	.1909	6.061	98.36	.1899
130	8.367	98.42	.1933	7.560	99.99	.1947	6.795	99.98	.1936	6.168	99.96	.1925
140	8.522	100.01	.1960	7.689	101.60	0.1974	6.912	101.58	0.1962	6.274	101.57	0.1952
150	8.667	101.62	0.1986	7.818	103.22	.2000	7.029	103.20	.1989	6.380	103.19	.1978
160	8.812	103.23	.2013	7.947	104.85	.2026	7.146	104.83	.2015	6.485	104.82	.2004
170	8.957	104.86	.2039	8.076	106.49	.2052	7.263	106.48	.2041	6.589	106.47	.2030
180	9.102	106.51	.2065	8.205	108.14	.2078	7.380	108.13	.2066	6.795	108.12	.2056
190	9.247	108.16	.2091	8.334	109.81	0.2103	7.497	109.80	0.2092	6.801	109.78	0.2081
200	9.387	109.82	0.2116	8.463	111.49	.2128	7.614	111.48	.2117	6.907	111.46	.2107
210	9.532	111.50	.2141	8.592	113.18	.2153	7.731	113.16	.2142	7.013	113.15	.2132
220	9.677	113.19	.2166	8.721	114.88	.2178	7.848	114.86	.2167	7.120	114.84	.2157
230	9.822	114.88	.2191	8.850	116.59	.2203	7.965	116.57	.2192	7.226	116.55	.2181
240	9.967	116.59	.2216	8.979	118.31	0.2228	8.082	118.29	0.2216	7.332	118.27	0.2206
250	10.11	118.31	0.2240	9.108	120.03	.2252	8.199	120.02	.2240	7.438	120.00	.2230
260	10.25	120.04	.2264	9.237	121.77	.2276	8.316	121.76	.2264	7.544	121.74	.2254
270	10.40	121.78	.2288	9.366	123.52	.2300	8.432	123.51	.2288	7.651	123.49	.2278
280	10.54	123.53	.2312	9.495	125.29	.2323	8.548	125.28	.2312	7.758	125.26	.2302
290	10.69	125.30	.2336	9.624	127.08	0.2347	8.664	127.07	0.2336	7.864	127.05	0.2325
300	10.83	127.09	0.2359	9.753	128.88	.2370	8.771	128.86	.2359	7.970	128.85	.2349
310	10.97	128.88	.2383	9.882	130.68	.2394	8.887	130.67	.2383	8.077	130.65	.2372
320	11.12	130.68	.2406	10.01	132.49	.2417	9.003	132.48	.2406	8.182	132.47	.2395
330	11.26	132.50	.2429	10.14	134.32	.2440	9.120	134.31	.2429	8.287	134.29	.2418
340	11.40	134.32	.2452	10.27	136.16	0.2463	9.236	136.14	0.2451	8.392	136.13	0.2441
350	11.54	136.16	0.2475	10.39	138.01	.2485	9.352	137.99	.2474	8.497	137.98	.2464
360	11.69	138.01	0.2498	10.52	139.86	0.2508	9.468	139.85	0.2497	8.602	139.84	0.2486
370
Temp. ° F.	Abs. Pressure 6.0 lb./in. ² Gauge Pressure 17.71 in. Vac. (Sat'n. Temp. 73.7° F.)			Abs. Pressure 6.5 lb./in. ² Gauge Pressure 16.69 in. Vac. (Sat'n. Temp. 77.3° F.)			Abs. Pressure 7.0 lb./in. ² Gauge Pressure 15.67 in. Vac. (Sat'n. Temp. 80.6° F.)			Abs. Pressure 7.5 lb./in. ² Gauge Pressure 14.65 in. Vac. (Sat'n. Temp. 83.8° F.)		
(At sat'n.)	(5.004)	(89.58)	(0.1735)	(4.616)	(90.10)	(0.1735)	(4.338)	(90.60)	(0.1736)	(4.064)	(91.06)	(0.1738)
80	5.066	90.54	0.1751	4.671	90.52	0.1743	4.393	90.52	0.1751	4.111	92.03	0.1755
90	5.163	92.08	.1779	4.762	92.06	.1771	4.414	92.05	0.1763	4.111	92.03	0.1755
100	5.260	93.62	0.1807	4.853	93.60	0.1799	4.498	93.60	0.1791	4.190	93.58	0.1783
110	5.357	95.18	.1835	4.944	95.16	.1827	4.581	95.16	.1818	4.269	95.14	.1811
120	5.454	96.76	.1862	5.035	96.74	.1854	4.666	96.73	.1845	4.348	96.71	.1838
130	5.551	98.35	.1889	5.125	98.33	.1881	4.749	98.32	.1872	4.427	98.30	.1865
140	5.649	99.95	.1916	5.215	99.93	.1908	4.834	99.91	.1899	4.507	99.90	.1892
150	5.746	101.56	0.1943	5.305	101.54	0.1934	4.919	101.52	0.1926	4.585	101.50	0.1919
160	5.843	103.17	.1969	5.394	103.16	.1961	5.003	103.14	.1952	4.663	103.12	.1945
170	5.940	104.80	.1995	5.484	104.79	.1987	5.086	104.77	.1978	4.741	104.75	.1971
180	6.037	106.45	.2021	5.573	106.43	.2013	5.169	106.42	.2004	4.819	106.40	.1997
190	6.134	108.10	.2047	5.663	108.09	.2038	5.253	108.07	.2030	4.897	108.05	.2023
200	6.233	109.77	0.2072	5.752	109.75	0.2064	5.337	109.73	0.2056	4.975	109.72	0.2048
210	6.330	111.44	.2097	5.841	111.43	.2089	5.420	111.41	.2081	5.053	111.39	.2073
220	6.427	113.13	.2122	5.930	113.11	.2114	5.504	113.10	.2106	5.131	113.08	.2098
230	6.525	114.83	.2147	6.021	114.81	.2139	5.587	114.80	.2131	5.209	114.78	.2123
240	6.622	116.54	.2172	6.110	116.52	.2164	5.671	116.50	.2156	5.286	116.49	.2148
250	6.719	118.26	0.2197	6.200	118.24	0.2188	5.755	118.22	0.2180	5.365	118.21	0.2173
260	6.816	119.99	.2221	6.290	119.97	.2212	5.838	119.95	.2204	5.444	119.94	.2197
270	6.913	121.73	.2245	6.381	121.71	.2236	5.921	121.69	.2228	5.523	121.68	.2221
280	7.011	123.48	.2269	6.470	123.46	.2260	6.004	123.45	.2252	5.602	123.44	.2245
290	7.108	125.25	.2293	6.558	125.23	.2284	6.087	125.22	.2276	5.680	125.21	.2269
300	7.205	127.04	0.2316	6.647	127.02	0.2308	6.170	127.01	0.2300	5.757	127.00	0.2292
310	7.302	128.84	.2340	6.737	128.82	.2331	6.254	128.81	.2323	5.834	128.80	.2316
320	7.398	130.64	.2363	6.827	130.63	.2354	6.337	130.61	.2346	5.911	130.60	.2339
330	7.495	132.46	.2386	6.917	132.44	.2377	6.420	132.43	.2370	5.988	132.42	.2362
340	7.591	134.28	.2409	7.008	134.27	.2400	6.504	134.26	.2393	6.064	134.24	.2385
350	7.687	136.12	0.2432	7.097	136.11	0.2423	6.587	136.09	0.2415	6.142	136.08	0.2408
360	7.784	137.97	.2455	7.186	137.96	.2446	6.670	137.94	.2438	6.221	137.93	.2431
370	7.880	139.83	.2477	7.274	139.82	.2469	6.752	139.80	.2461	6.299	139.79	.2453
380	7.975	141.70	0.2500	7.362	141.69	0.2491	6.834	141.68	.2483	6.378	141.67	.2476
390	6.916	143.57	0.2506	6.457	143.56	0.2498

PROPERTIES OF SUPERHEATED VAPOR—Continued

Temp. ° F.	Abs. Pressure 8.0 lb./in. ² Gauge Pressure 13.64 in. Vac. (Sat'n. Temp. 85.9° F.)			Abs. Pressure 9.0 lb./in. ² Gauge Pressure 11.60 in. Vac. (Sat'n. Temp. 92.5° F.)			Abs. Pressure 10.0 lb./in. ² Gauge Pressure 9.57 in. Vac. (Sat'n. Temp. 97.6° F.)			Abs. Pressure 11 lb./in. ² Gauge Pressure 7.53 in. Vac. (Sat'n. Temp. 102.4° F.)		
	V	H	S	V	H	S	V	H	S	V	H	S
(At sat'n.)	(3.828)	(91.52)	(0.1739)	(3.431)	(92.35)	(0.1742)	(3.110)	(93.11)	(0.1745)	(2.845)	(93.81)	(0.1747)
90	3.850	92.01	0.1748
100	3.924	93.56	0.1776	3.481	93.52	0.1763	3.124	93.48	0.1751
110	3.999	95.12	.1804	3.547	95.08	.1791	3.183	95.04	.1779	2.887	95.01	0.1769
120	4.073	96.69	.1831	3.613	96.66	.1819	3.242	96.62	.1806	2.941	96.58	.1796
130	4.147	98.28	.1858	3.679	98.25	.1846	3.301	98.21	.1834	3.005	98.17	.1823
140	4.221	99.88	.1885	3.745	99.84	.1872	3.361	99.81	.1860	3.049	99.77	.1850
150	4.295	101.48	0.1912	3.810	101.45	0.1899	3.420	101.41	0.1887	3.103	101.38	0.1877
160	4.369	103.10	.1938	3.874	103.07	.1925	3.480	103.03	.1914	3.157	103.00	.1903
170	4.442	104.74	.1964	3.940	104.70	.1951	3.539	104.66	.1940	3.211	104.63	.1929
180	4.515	106.38	.1990	4.004	106.34	.1977	3.599	106.31	.1966	3.265	106.28	.1955
190	4.588	108.04	.2016	4.070	108.00	.2003	3.658	107.96	.1991	3.319	107.93	.1981
200	4.661	109.71	0.2041	4.135	109.67	0.2028	3.716	109.63	0.2017	3.373	109.60	0.2006
210	4.734	111.38	.2066	4.199	111.35	.2054	3.774	111.32	.2042	3.426	111.28	.2032
220	4.807	113.07	.2091	4.265	113.04	.2079	3.832	113.01	.2067	3.480	112.97	.2057
230	4.880	114.77	.2116	4.330	114.74	.2104	3.891	114.71	.2092	3.533	114.67	.2082
240	4.952	116.48	.2141	4.395	116.45	.2129	3.950	116.42	.2117	3.586	116.38	.2106
250	5.024	118.20	0.2166	4.460	118.17	0.2153	4.010	118.14	0.2141	3.639	118.10	0.2131
260	5.096	119.93	.2190	4.525	119.91	.2177	4.068	119.87	.2166	3.692	119.84	.2155
270	5.168	121.67	.2214	4.590	121.64	.2201	4.126	121.61	.2190	3.745	121.58	.2179
280	5.240	123.42	.2238	4.656	123.40	.2225	4.185	123.37	.2214	3.798	123.34	.2203
290	5.313	125.19	.2261	4.721	125.17	.2249	4.243	125.15	.2237	3.852	125.12	.2227
300	5.387	126.98	0.2285	4.787	126.96	0.2273	4.302	126.94	0.2261	3.906	126.91	0.2250
310	5.460	128.78	.2309	4.852	128.76	.2296	4.360	128.74	.2285	3.960	128.71	.2274
320	5.533	130.58	.2332	4.918	130.57	.2319	4.419	130.54	.2308	4.014	130.51	.2298
330	5.607	132.40	.2355	4.983	132.39	.2343	4.477	132.36	.2331	4.068	132.33	.2321
340	5.682	134.23	.2378	5.048	134.21	.2366	4.537	134.19	.2354	4.122	134.16	.2344
350	5.756	136.07	0.2401	5.112	136.05	0.2388	4.596	136.03	0.2377	4.175	136.00	0.2367
360	5.830	137.92	.2424	5.178	137.90	.2411	4.656	137.88	.2400	4.229	137.85	.2389
370	5.904	139.78	.2447	5.243	139.76	.2434	4.714	139.74	.2422	4.283	139.71	.2412
380	5.975	141.66	.2470	5.307	141.64	.2456	4.772	141.62	.2445	4.336	141.59	.2434
390	6.047	143.55	0.2492	5.372	143.52	.2479	4.829	143.50	.2467	4.389	143.48	.2457
400	5.436	145.41	0.2501	4.887	145.39	0.2489	4.441	145.37	0.2479
410	4.493	147.28	0.2501
Temp. ° F.	Abs. Pressure 12 lb./in. ² Gauge Pressure 5.50 in. Vac. (Sat'n. Temp. 106.8° F.)			Abs. Pressure 13 lb./in. ² Gauge Pressure 3.46 in. Vac. (Sat'n. Temp. 111.0° F.)			Abs. Pressure 14 lb./in. ² Gauge Pressure 1.42 in. Vac. (Sat'n. Temp. 114.9° F.)			Abs. Pressure 16 lb./in. ² Gauge Pressure 1.3 lb./in. ² (Sat'n. Temp. 122.1° F.)		
(At sat'n.)	(2.624)	(94.46)	(0.1750)	(2.435)	(95.08)	(0.1753)	(2.271)	(95.60)	(0.1755)	(2.004)	(96.72)	(0.1760)
110	2.640	94.97	0.1759
120	2.689	96.55	.1786	2.477	96.51	0.1778	2.291	96.47	0.1770
130	2.738	98.14	.1813	2.522	98.10	.1805	2.334	98.06	.1797	2.034	97.99	0.1782
140	2.788	99.73	.1840	2.567	99.70	.1832	2.377	99.66	.1823	2.072	99.59	.1809
150	2.838	101.34	0.1867	2.613	101.31	0.1858	2.421	101.27	0.1850	2.110	101.20	0.1835
160	2.888	102.97	.1894	2.659	102.94	.1885	2.465	102.90	.1876	2.148	102.83	.1862
170	2.938	104.60	.1920	2.704	104.57	.1911	2.508	104.53	.1902	2.186	104.46	.1888
180	2.987	106.25	.1946	2.749	106.21	.1937	2.550	106.18	.1928	2.224	106.11	.1914
190	3.037	107.90	.1972	2.795	107.87	.1963	2.593	107.84	.1954	2.262	107.77	.1940
200	3.086	109.57	0.1997	2.841	109.54	0.1988	2.635	109.51	0.1980	2.299	109.44	0.1965
210	3.135	111.26	.2022	2.887	111.23	.2013	2.678	111.20	.2005	2.336	111.13	.1991
220	3.184	112.95	.2047	2.933	112.92	.2039	2.720	112.89	.2030	2.374	112.83	.2016
230	3.234	114.65	.2072	2.979	114.62	.2064	2.763	114.59	.2055	2.411	114.53	.2041
240	3.283	116.36	.2097	3.025	116.33	.2088	2.806	116.30	.2080	2.448	116.24	.2065
250	3.332	118.08	0.2121	3.071	118.05	0.2113	2.848	118.02	0.2105	2.486	117.96	0.2090
260	3.382	119.81	.2146	3.117	119.79	.2137	2.890	119.76	.2129	2.523	119.70	.2114
270	3.431	121.55	.2170	3.162	121.53	.2162	2.932	121.50	.2153	2.560	121.45	.2138
280	3.479	123.31	.2194	3.208	123.29	.2186	2.975	123.26	.2177	2.596	123.21	.2162
290	3.528	125.09	.2218	3.254	125.07	.2209	3.018	125.04	.2201	2.633	124.99	.2186
300	3.578	126.88	0.2241	3.300	126.86	0.2232	3.060	126.84	0.2225	2.671	126.78	0.2210
310	3.627	128.68	.2265	3.345	128.66	.2256	3.103	128.64	.2248	2.709	128.58	.2233
320	3.676	130.49	.2288	3.391	130.47	.2279	3.145	130.44	.2271	2.746	130.39	.2257
330	3.725	132.31	.2311	3.436	132.29	.2302	3.187	132.26	.2294	2.783	132.21	.2280
340	3.774	134.14	.2334	3.481	134.12	.2325	3.229	134.09	.2317	2.820	134.04	.2303
350	3.823	135.98	0.2357	3.526	135.96	0.2348	3.271	135.94	0.2340	2.857	135.88	0.2326
360	3.872	137.83	.2380	3.572	137.81	.2371	3.313	137.79	.2363	2.895	137.74	.2349
370	3.922	139.69	.2402	3.617	139.68	.2394	3.355	139.65	.2386	2.932	139.60	.2371
380	3.972	141.57	.2425	3.662	141.56	.2416	3.397	141.52	.2408	2.968	141.47	.2394
390	4.021	143.45	.2447	3.707	143.44	.2439	3.439	143.41	.2430	3.005	143.36	.2416
400	4.069	145.34	0.2469	3.752	145.33	0.2461	3.481	145.31	0.2453	3.042	145.26	0.2438
410	4.117	147.25	0.2491	3.797	147.24	.2483	3.522	147.22	.2475	3.079	147.17	.2460
420	3.841	149.16	0.2505	3.562	149.14	0.2497	3.115	149.10	.2482
430	3.152	151.03	0.2504

PROPERTIES OF SUPERHEATED VAPOR—Continued

Temp. ° F.	Abs. Pressure 18 lb./in. ² Gauge Pressure 3.3 lb./in. ² (Sat'n. Temp. 133.6° F.)			Abs. Pressure 20 lb./in. ² Gauge Pressure 5.3 lb./in. ² (Sat'n. Temp. 134.6° F.)			Abs. Pressure 25 lb./in. ² Gauge Pressure 10.3 lb./in. ² (Sat'n. Temp. 147.3° F.)			Abs. Pressure 30 lb./in. ² Gauge Pressure 15.3 lb./in. ² (Sat'n. Temp. 159.1° F.)		
	v	h	s	v	h	s	v	h	s	v	h	s
(At sat'n.)	(1.795)	(97.68)	(0.1769)	(1.825)	(98.56)	(0.1769)	(1.847)	(100.50)	(0.1778)	(1.109)	(102.15)	(0.1787)
130	1.799	97.91	0.1769
140	1.833	99.51	.1795	1.640	99.43	0.1783
150	1.867	101.12	0.1822	1.672	101.05	0.1810	1.322	100.87	0.1784
160	1.901	102.75	.1848	1.703	102.68	.1826	1.348	102.50	.1811	1.111	102.31	0.1790
170	1.935	104.39	.1875	1.734	104.32	.1862	1.373	104.14	.1837	1.132	103.96	.1816
180	1.968	106.04	.1901	1.765	105.97	.1888	1.398	105.80	.1863	1.153	105.62	.1842
190	2.002	107.71	.1926	1.796	107.64	.1914	1.423	107.47	.1889	1.173	107.29	.1868
200	2.036	109.39	0.1952	1.827	109.32	0.1940	1.448	109.15	0.1915	1.194	108.97	0.1894
210	2.069	111.08	.1977	1.857	111.01	.1966	1.472	110.84	.1940	1.215	110.67	.1919
220	2.103	112.77	.2003	1.887	112.70	.1991	1.497	112.54	.1966	1.236	112.37	.1945
230	2.136	114.47	.2028	1.917	114.40	.2016	1.522	114.25	.1991	1.257	114.08	.1970
240	2.169	116.18	.2052	1.947	116.12	.2041	1.546	115.96	.2015	1.278	115.80	.1995
250	2.203	117.90	0.2077	1.977	117.84	0.2065	1.571	117.69	0.2040	1.299	117.53	0.2019
260	2.236	119.64	.2101	2.007	119.58	.2090	1.595	119.44	.2064	1.320	119.28	.2044
270	2.269	121.39	.2125	2.037	121.33	.2114	1.619	121.19	.2089	1.341	121.03	.2068
280	2.303	123.15	.2149	2.068	123.09	.2138	1.643	122.95	.2113	1.362	122.80	.2092
290	2.336	124.92	.2173	2.098	124.87	.2162	1.667	124.73	.2137	1.382	124.59	.2116
300	2.370	126.72	0.2197	2.128	126.67	0.2185	1.691	126.53	0.2160	1.402	126.39	0.2140
310	2.403	128.53	.2220	2.158	128.47	.2209	1.716	128.34	.2184	1.422	128.20	.2163
320	2.436	130.34	.2244	2.187	130.28	.2232	1.741	130.16	.2207	1.442	130.02	.2187
330	2.469	132.16	.2267	2.217	132.10	.2255	1.765	131.98	.2231	1.462	131.85	.2210
340	2.502	133.99	.2290	2.247	133.94	.2278	1.789	133.82	.2254	1.483	133.69	.2233
350	2.535	135.83	0.2313	2.277	135.78	0.2301	1.813	135.66	0.2277	1.503	135.54	0.2256
360	2.569	137.69	.2336	2.308	137.64	.2324	1.838	137.52	.2300	1.524	137.40	.2279
370	2.602	139.55	.2358	2.338	139.50	.2347	1.862	139.39	.2322	1.545	139.27	.2302
380	2.635	141.43	.2381	2.368	141.38	.2369	1.886	141.26	.2345	1.565	141.15	.2324
390	2.667	143.32	.2403	2.398	143.27	.2392	1.910	143.15	.2367	1.585	143.05	.2347
400	2.700	145.22	0.2425	2.427	145.17	0.2414	1.933	145.05	0.2389	1.604	144.95	0.2369
410	2.733	147.13	.2447	2.456	147.08	.2436	1.957	146.97	.2411	1.624	146.86	.2391
420	2.765	149.05	.2469	2.485	149.01	.2458	1.981	148.90	.2433	1.645	148.79	.2413
430	2.797	150.99	0.2491	2.515	150.94	.2480	2.005	150.83	.2455	1.665	150.73	.2435
440	2.544	152.89	0.2501	2.029	152.78	.2477	1.685	152.68	.2457
450	2.052	154.74	0.2498	1.706	154.65	0.2479
460	1.726	156.62	0.2500
Temp. ° F.	Abs. Pressure 35 lb./in. ² Gauge Pressure 20.3 lb./in. ² (Sat'n. Temp. 169.0° F.)			Abs. Pressure 40 lb./in. ² Gauge Pressure 25.3 lb./in. ² (Sat'n. Temp. 177.9° F.)			Abs. Pressure 50 lb./in. ² Gauge Pressure 35.3 lb./in. ² (Sat'n. Temp. 194.5° F.)			Abs. Pressure 60 lb./in. ² Gauge Pressure 45.3 lb./in. ² (Sat'n. Temp. 206.9° F.)		
(At sat'n.)	(0.9589)	(102.60)	(0.1795)	(0.8435)	(104.90)	(0.1802)	(0.6809)	(107.14)	(0.1816)	(0.5705)	(109.06)	(0.1827)
170	0.9594	103.77	0.1797
180	0.9780	105.43	.1824	0.8462	105.26	0.1808
190	0.9963	107.10	.1850	.8627	106.94	.1834
200	1.015	108.79	0.1876	0.8791	108.62	0.1860	0.6899	108.27	0.1833
210	1.033	110.49	.1901	.8953	110.32	.1885	.7031	109.97	.1858	0.5738	109.60	0.1835
220	1.051	112.20	.1927	.9114	112.03	.1911	.7163	111.69	.1884	.5853	111.31	.1861
230	1.069	113.91	.1952	.9274	113.74	.1936	.7296	113.41	.1909	.5968	113.04	.1886
240	1.088	115.63	.1977	.9435	115.47	.1961	.7430	115.14	.1934	.6082	114.78	.1912
250	1.106	117.37	0.2002	0.9596	117.21	0.1986	0.7562	116.90	0.1959	0.6193	116.54	0.1937
260	1.124	119.12	.2026	.9756	118.97	.2010	.7693	118.67	.1984	.6303	118.32	.1961
270	1.142	120.88	.2051	0.9915	120.74	.2035	.7821	120.45	.2008	.6413	120.11	.1986
280	1.160	122.66	.2075	1.008	122.52	.2059	.7950	122.23	.2033	.6525	121.91	.2010
290	1.177	124.45	.2099	1.023	124.31	.2088	.8079	124.03	.2057	.6639	123.72	.2035
300	1.195	126.26	0.2122	1.038	126.12	0.2107	0.8207	125.84	0.2081	0.6751	125.53	0.2059
310	1.212	128.07	.2146	1.054	127.94	.2131	.8335	127.66	.2104	.6860	127.36	.2083
320	1.230	129.89	.2169	1.070	129.76	.2154	.8463	129.48	.2128	.6969	129.19	.2106
330	1.248	131.72	.2193	1.085	131.59	.2178	.8591	131.31	.2152	.7079	131.03	.2130
340	1.266	133.56	.2216	1.101	133.44	.2201	.8716	133.16	.2175	.7188	132.89	.2153
350	1.284	135.41	0.2239	1.117	135.29	0.2224	0.8844	135.02	0.2198	0.7296	134.75	0.2176
360	1.302	137.27	.2262	1.133	137.16	.2247	.8973	136.89	.2221	.7403	136.63	.2199
370	1.319	139.15	.2285	1.148	139.03	.2269	.9101	138.77	.2244	.7510	138.52	.2222
380	1.336	141.03	.2307	1.164	140.91	.2292	.9228	140.67	.2266	.7619	140.42	.2245
390	1.353	142.93	.2329	1.179	142.81	.2314	.9354	142.57	.2289	.7725	142.33	.2267
400	1.370	144.83	0.2352	1.194	144.72	0.2337	0.9480	144.48	0.2311	0.7831	144.24	0.2290
410	1.388	146.75	.2374	1.210	146.64	.2359	.9605	146.41	.2333	.7937	146.16	.2312
420	1.405	148.68	.2396	1.225	148.57	.2381	.9728	148.35	.2356	.8043	148.10	.2334
430	1.422	150.62	.2418	1.240	150.51	.2403	.9851	150.30	.2378	.8151	150.06	.2356
440	1.439	152.58	.2440	1.256	152.47	.2425	0.9974	152.25	.2400	.8257	152.02	.2378
450	1.457	154.54	0.2461	1.271	154.44	0.2447	1.010	154.22	0.2421	0.8362	154.00	0.2400
460	1.474	156.52	.2483	1.286	156.41	.2468	1.023	156.21	.2443	.8466	155.98	.2422
470	1.491	158.51	0.2505	1.302	158.40	.2490	1.036	158.20	.2464	.8570	157.98	.2443
480	1.317	160.40	0.2511	1.048	160.20	.2486	.8675	159.98	.2465
490	1.060	162.22	.2507	.8776	162.00	.2486
500	1.072	164.24	0.2528	0.8880	164.03	0.2508
510	0.8987	166.07	0.2529

CLOSED ELECTRICAL APPARATUS CABINET
EMBODYING A VAPORIZATION CHAMBER
AND CABINET TOP THEREOF

ABSTRACT OF THE DISCLOSURE

A cabinet for electrical equipment to be protected from a hostile environment comprising a sealed top section consisting of a vaporization chamber containing trichlorotrifluoroethane, with the upper surface having a generally recessed polyhedral shape to promote accumulation of condensate at the roof of the vaporization chamber to replenish the liquid to the chamber base.

BACKGROUND OF THE INVENTION

10 This invention relates to a housing for electrical apparatus providing, in an overall light and rigid structure, total isolation of the electrical apparatus from ambient conditions while preserving excellent heat transfer proficiency.

When electrical apparatus must be placed inside an enclosure, it is necessary to prevent temperature build-up due to heat accumulation in, or around, the electrical parts. Usually external air is blown inside and through the enclosure in order to evacuate the accumulated heat. However, it is not desirable to do so when the equipment is operated in a dirty, 20 hostile atmosphere, since particles introduced into the enclosure could cause electrical defects.

It is known to cool electrical equipment with air-to-air or liquid-to-liquid or liquid-to-air heat exchangers in direct contact with the critical electrical parts (for instance electrodes) or rather with a heat sink, in order to remove the heat toward a heat dissipator.

It is also known to remove the heat of an electrical apparatus with a heat pipe, e.g. a sealed off device containing a liquid which is vaporized on a side exposed to the heat sink, and condensed on the side exposed to the heat dissipator. Vaporization chambers are known which contain a fluid which takes up heat by vaporization against a hot wall, the vapor being spread onto a cool wall where it is being condensed and returned by gravity for reuse along the hot wall thereof. The essential distinction between a heat pipe and a vaporization chamber, resides in that the former carries away the vaporized fluid and returns the condensate across a smaller cross section and along a longer path, sometimes with the assist of a wick element utilizing capillary action.

SUMMARY OF THE INVENTION

The present invention resides in using a vaporization chamber as the top section of an enclosure housing totally enclosed electrical apparatus, so that the heat generated by the electrical apparatus is absorbed by the lower surface of the vaporization chamber, while the condensate of the vapor-

ized fluid is being returned by gravity from the top surface of the vaporization chamber used as a heat dissipator.

The invention distinguishes over vaporization chamber, or heat pipes, of the prior art in that the cooling structure itself is part of the overall housing structure of the electrical apparatus, rather than being merely a cooling device embodied within a predetermined vessel structure. The invention also provides for a working fluid within the vaporization chamber having a temperature of vaporization
10 at one atmosphere pressure which is under the critical temperature of the enclosed electric apparatus so that the vapor build-up within the vaporization chamber substantially remains at the ambient atmospheric pressure. As a result, no particular reinforcing structure is needed, in general, for the vaporization chamber.

The invention, further provides that the metallic wall defining the surfaces of the vaporization chamber, in particular the heat evaporator and the heat dissipator of the vaporization chamber, are given a minimum thickness, with the additional
20 feature that areas of the heat dissipator are inclined at an angle to the overall horizontal plane of the top surface which create internal protrusions in the vaporization chamber which provide condensate return by gravity from the heat dissipator, or condenser, to the surface of the working fluid, while at the same time providing structural reinforce-

ment compensating for the minimum thickness chosen. As a result, maximum heat dissipation at the top surface and maximum condensate return circulation are obtained in conjunction with improving the housing structure solidity.

The invention will be more fully understood from a consideration of the preferred embodiment described hereinafter as an illustration of how the invention can best be readily carried into practice.

BRIEF DESCRIPTION OF THE DRAWINGS

10 Figure 1 shows the cabinet according to the present invention.

Figure 2 show another illustration of the present invention with an amovable vaporization chamber forming the top section of a cabinet containing electrical equipment to be protected from the outside.

THE PREFERRED EMBODIMENT OF THE INVENTION

Figure 1 represents an electrical cabinet for electrical apparatus, preferrable for computer equipment, defined between a top surface having four apices 1, 2, 3, 4 and
 20 a bottom surface having four apices 9, 10, 11, 12. This cabinet has seal-proof metallic walls (1, 2, 3, 4) (9, 10, 11, 12) (1, 4, 9, 12), (4, 12, 11, 3), (10, 11, 3, 2) and (9, 10, 2, 1), within which two sealed compartments AR and VC are provided. The AR compartment contains the electrical equipment in the form of electronic components

and electrical supply thereof, mounted on racks (not shown) across the vertical walls. Preferably, the AR compartment contains the entire package of a minicomputer.

The VC compartment is sealed and constitutes essentially a vaporization chamber defined between planes (5, 8, 7, 6) and (1, 2, 3, 4) at the top of the cabinet. A sufficient quantity of trichlorotrifluoroethane (Freon 113) or other suitable working fluid is enclosed within compartment VC so as to maintain at all times a layer of liquid on the lower
10 surface (5, 6, 7, 8) even when some of the liquid has been vaporized therefrom. This layer is replenished by liquid which is continuously returned in the form of condensate from beneath the top surface (1, 2, 3, 4) i.e., a continuous cyclic flow of working fluid is created.

The temperature of vaporization of Freon 113 is 117°f at 0 p.s.i.g. (47°C at one atmosphere).

The apparatus enclosed in the AR compartment may for instance be a computer, its power supply and auxiliary circuitry. It is desirable that the equipment contained
20 in the cabinet not be subjected to temperatures 132°F (55°C). This would require an evacuation of excess heat through the heat sink or condenser surface (5, 6, 7, 8) of the vaporization chamber in the order of 1.5 to w kilowatts. Considering the usual dimensions of a minicomputer with properly distributed racks of components, this excess of heat represents

an evacuation of the order of 3 watts/square inch of the heat sink surface or more, depending on cabinet dimensions. For such requirement, the distance between the two planes defining the heat sink and heat dissipator of the vaporization chamber VC is selected to be between 2 and 6 inches when Freon 113 is used as the working fluid.

The thermodynamics of operation of a vaporization chamber is well known. The heat received through the heat sink (5, 6, 7, 8) converts an equivalent quantity of liquid into vapor (latent heat of vaporization) which reaches the cooler surface of the heat dissipator and gives up its latent heat, then condenses and falls back back by gravity to the liquid reservoir. This process is self-sustaining and no exterior means other than the presence of a temperature gradient are necessary to evacuate the heated medium or supply working fluid to the reservoir, as would be the case in a normal heat exchanger using pumps or fans to move the working fluid. Gravity dispenses from the provision of any particular means to force the circulation of the cooling medium.

20 The choice of Freon 113 allows the vaporization chamber to be operative at normal atmospheric pressure at a given temperature range. Therefore, there is no build-up of pressure inside the sealed compartment VC which otherwise would require reinforced wall structures. Normal cabinet walls can be used

and the vaporization chamber may be self-contained and assembled to form the top section of the cabinet structure.

In addition, special provision is made of a thin metallic wall for such cabinet structure. For instance an aluminum sheet can be used. The thinness of the metal is favorable in providing maximum efficiency in the heat transfer both for the heat sink or evaporator (5. 6. 7. 8) and the heat dissipator, or condenser (1, 2, 3, 4). This requirement of a thin wall is satisfied, in accordance with the present
10 invention, without any reduction in the overall cabinet strength by providing at the top-surface of the cabinet a certain configuration, as shown by planes A, B, D, C which are defined by creases formed in the metal and a dimple. This particular structural feature of the top of the cabinet enhances the efficiency of the vaporization chamber by presenting to the vaporized fluid inclined surfaces which tend to accelerate the formation of heavy accumulation of liquid and cause the condensate to run from the roof of the chamber down to the pool, or reservoir resting by gravity on the
20 heat sink or evaporator surface.

The cabinet, according to the present invention, is made of sheet metal for the side walls as well as for the top and the bottom sections. The heat dissipator of the vaporization chamber VC is a metal sheet which may be made integral with the four vertical cabinet walls. As earlier

explained, the thickness of the metal used is selected to be as small as acceptable for the cabinet strength in order to strengthen the top section of the cabinet while keeping such minimal acceptable metal thickness. As previously stated, inclined planes are formed to facilitate the return of the condensate by gravity from the heat dissipator down to the heat sink. The top surface may also be made disc-shaped, or incurvated, in any way to create and consist of a surface inclined downward from the periphery. A similar structural shape may also be formed in the opposite direction, e.g., upward to strengthen the heat sink or condensor metal plates.

Figure 1 shows four planes A, B, C, D defined by creases extending in the top metal sheet from the peripheral apices 1, 2, 3, 4, downward. As a result, the roof of the vaporization chamber VC has a generally polyhedral shape providing preferential directions of flow along which the condensate accumulates and runs back down to the mass of fluid in the liquid state.

The heat sink (5, 6, 7, 8) of the vaporization chamber preferably consists of a transverse plate of metal integrally united with the side walls of the cabinet. The vaporization chamber VC does not carry any appreciable weight, nor does it support any substantial pressure. It does not either occupy much space above the contained equipment. A unitary

closed cabinet is thus provided which carries a top section entirely sealed from the outside, and in which a heat transfer feature has been embodied as simply as possible, while only slightly changing the configuration and the overall dimensions of the cabinet without requiring the addition of any substantial part or weight, and that can easily be accommodated with a standard cabinet.

The present invention may be carried out in different forms shown in Figure 1. Figure 2 shows a typical top section for a cabinet according to the present invention. Figure 2 shows how typically the cabinet top according to the present invention is mounted on the upper part of the cabinet. The cabinet 20 is provided with flanges 21 along the upper part of the vertical metal plates on four sides of the enclosure in which electrical components of the enclosed apparatus are mounted. The top section 22 is in the form of a sealed vaporization chamber, containing working fluid which by gravity rests on the lower surface 23. The upper surface 24 of the top section 22 exhibits creases at 25 for the purpose described heretofore. Preferably, but not necessarily, creases at 26 are also provided in the metal sheet forming the lower surface 23. The heat sink, or evaporator, is constituted by the lower metal sheet 23, the heat dissipator, or condenser is found at 24 with the upper metal sheet of the top section 22. A platform 27 is provided which can be mounted easily

laterally of the top section on a supporting plate 32. On the platform are mounted pressure and temperature gauges 28, 29 which are in communication with the vaporization chamber through an access port 30, provided with a peripheral point 31 which can be sealed tight between the supporting plate 32 by bolts and screws 33.

It is possible to build vaporization chamber VC as a separate unit all sealed off in advance, and to build separately the equipment vessel AR with all parts mounted inside as another
10 unit. The two units are then assembled, mounted and joined integrally in order to form the cabinet according to the present invention.

Normally heat from the equipment vessel to the vaporization chamber is transferred to the heat sink by radiation, conduction, and convection. Provision can be made, not necessarily, for an electric fan within the equipment vessel AR, in order to force circulation of the air enclosed in the cabinet toward and along the surface of the heat sink (5, 6, 7, 8) in order to increase heat exchange with the vaporization
20 chamber.

It is also possible to include within the equipment vessel one or more additional vaporization chambers, each associated with specific electrical components or parts of greater concern. These additional chambers would abandon heat from their heat dissipator surfaces into the air space

inside the equipment enclosure. In this fashion cascaded cooling may take place from down with the equipment vessel AR up to the main heat sink surface (5, 6, 7, 8) of the main vaporization chamber VC according to the present invention.

CLAIMS

1 1. A cabinet for electrical equipment comprising an
2 enclosure having side walls and bottom surfaces, a partition
3 defining two compartments one on top of the other, the lower
4 compartment containing electrical equipment and the top
5 compartment being a sealed compartment forming a vaporization
6 chamber defined between said partition as a heat sink and a
7 heat dissipator serving as the top surface of said cabinet.

1 2. The cabinet of claim 1, with said vaporization
2 chamber containing liquid resting by gravity on said partition
3 and having a vaporization temperature above 80°F and below
4 120°F.

1 3. The cabinet of claim 2, with said liquid being
2 trichlorotrifluoroethane.

1 4. The cabinet of claim 2, with said top surface being
2 recessed from a horizontal plane defined by the highest points
3 of the sidewalls of said cabinet.

1 5. The cabinet of claim 4 with said top surface
2 having a plurality of planar surfaces inclined downward,
3 the form factors of which promote the return of the condensate
4 to the liquid on said partition.

1 6. The cabinet of claim 5 with said top surface being
2 made of metal sheet, and said planar surfaces being formed
3 by folding of said metal sheet.

1 7. A cabinet for electrical equipment comprising a
2 bottom wall, four vertical side walls, an amovable top
3 section adapted to be mounted directly on said side walls
4 to form a closed housing therewith, and means attached at
5 least to said side walls for supporting the electrical
6 equipment inside said closed housing; with said top section
7 consisting of a vaporization chamber.

1 8. The cabinet of claim 7 with said top section having
2 an upper metallic plate, a lower metallic plate and four
3 side plates, said upper, lower and side plates being integrally
4 united to form a sealed chamber containing liquid trichloro-
5 trifluoroethane resting by gravity on said lower surface.

1 9. The cabinet of claim 8 with said lower plate being
2 a heat sink for said cabinet, and with said higher plate
3 being a heat dissipator for said vaporization chamber.

1 10. The cabinet of claim 9 with said upper plate
2 having a plurality of planar surfaces inclined downward,
3 the form factors of which promote the return of the con-

4 densate from vapor evolving from said liquid.

1 11. The cabinet of claim 10 with said lower,

2 upper and side plates having a minimal thickness.

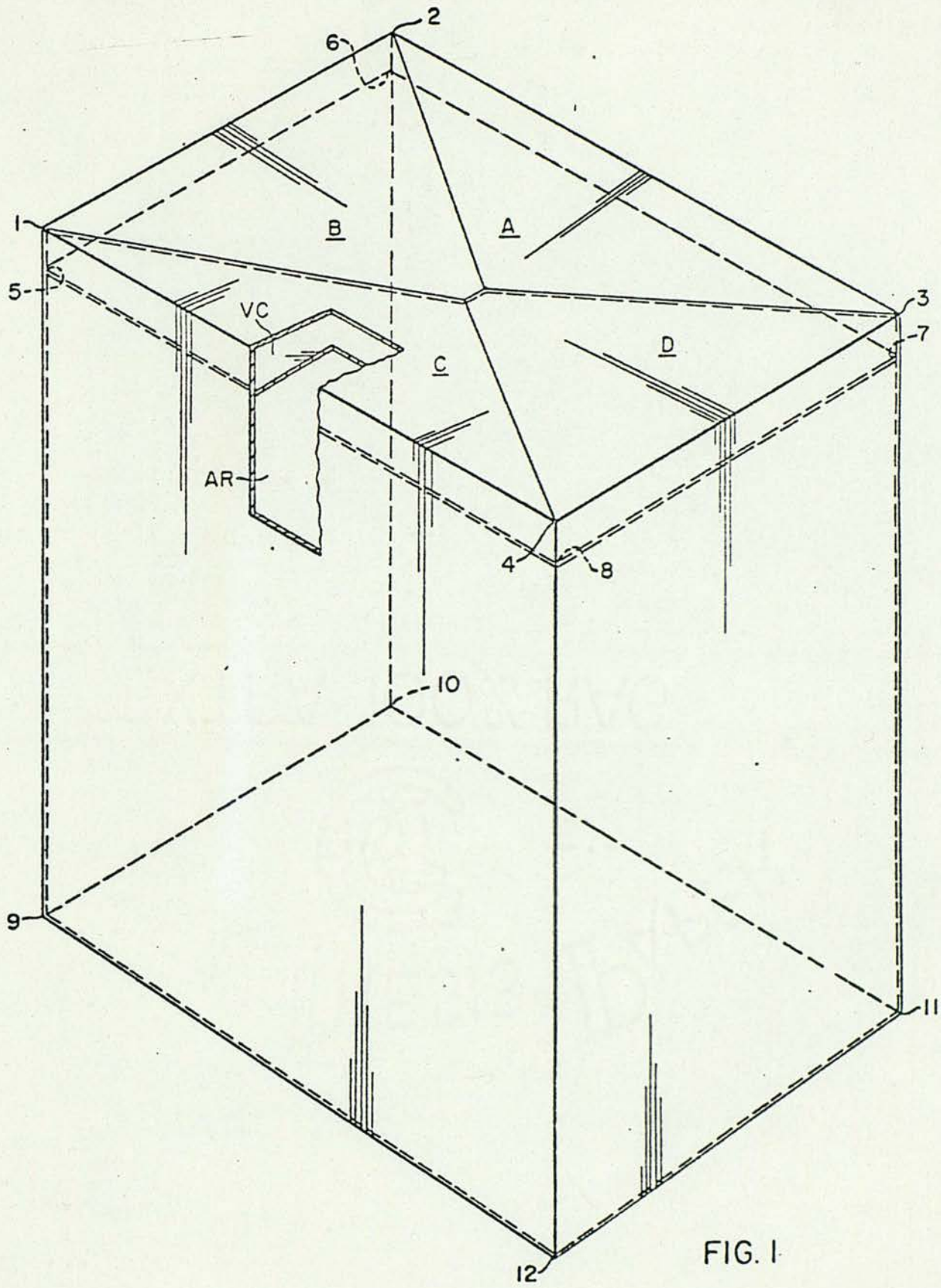


FIG. 1

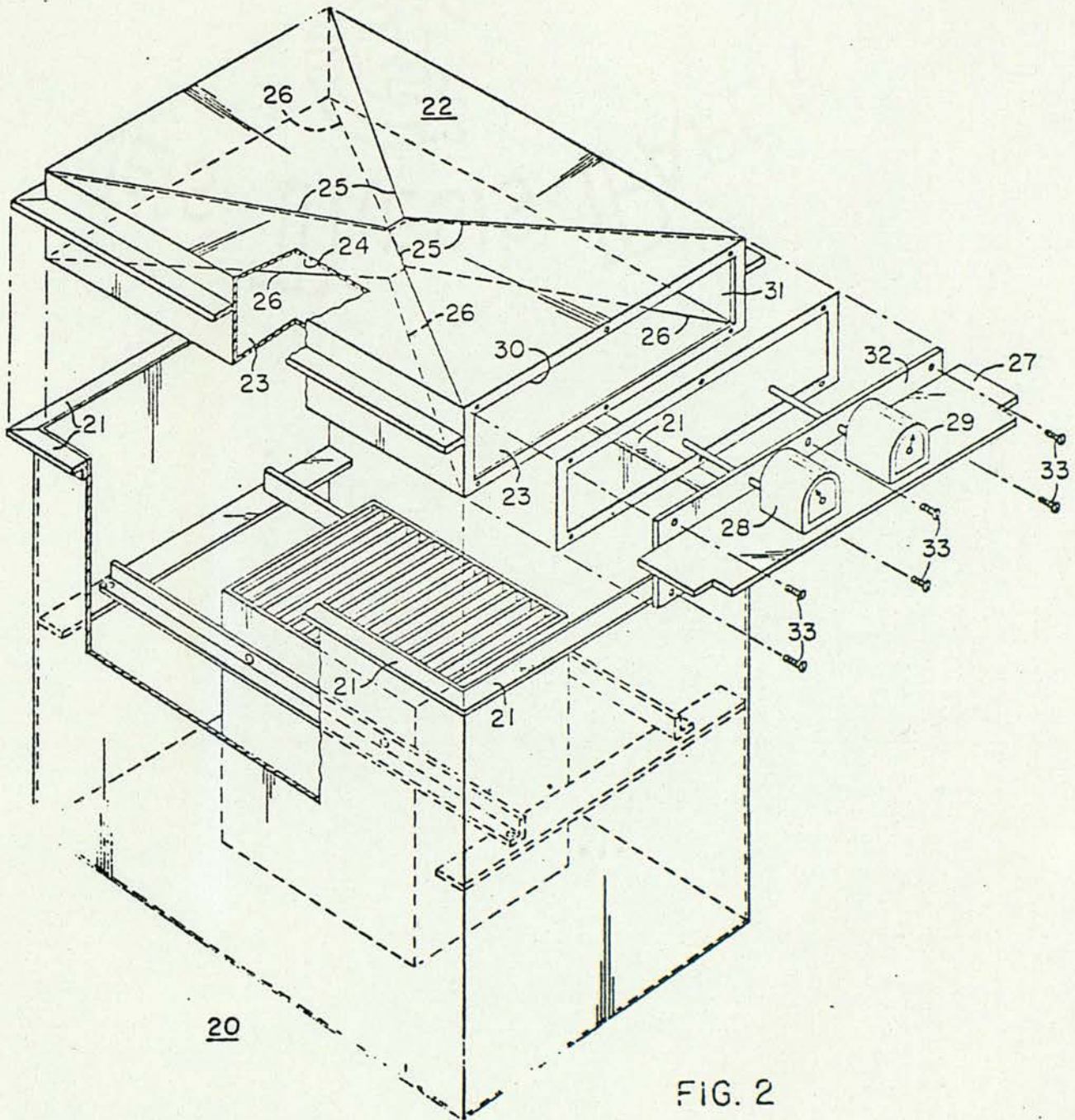


FIG. 2

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